Si5348 Rev E データシート

SyncE/ 1588 PTP テレコム・バウンダリ・クロック (T-BC) およびスレーブ・クロック (T-SC) 用ネットワーク・シンクロナイザ

Si5348 は、業界最小の設置面積および最小の消費電力のネットワーク・シンクロナイザ・クロックと、比類のない周波数合成の柔軟性と超低ジッタを同時に実現します。Si5348 は、従来およびパケット・ベースのネットワーク同期が必要なワイヤレス・バックホール、IP 無線、スモールセルおよびマクロセル・ワイヤレス通信システム、およびデータ・センター・スイッチに最適です。

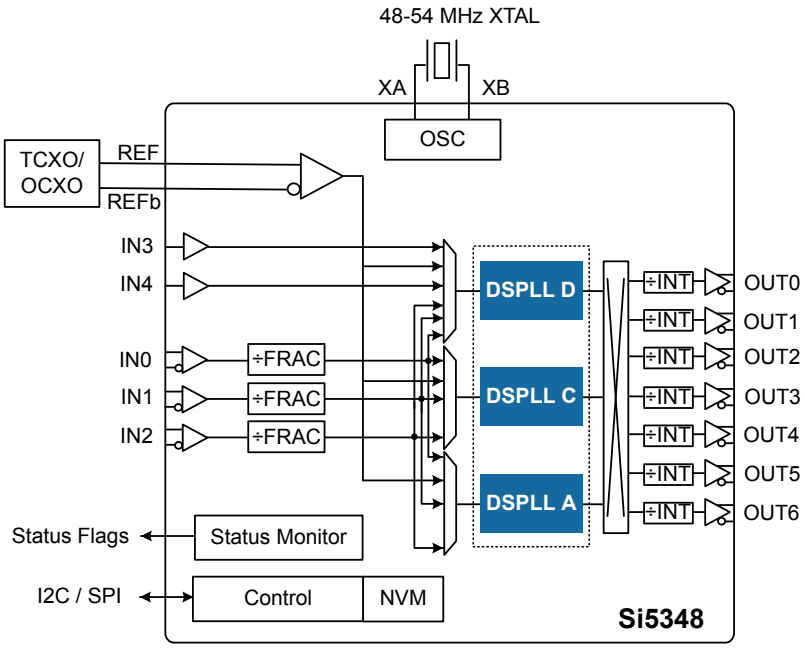
3 つの独立した DSPLL™ は、SyncE PLL、IEEE 1588 DCO、またはプロセッサ/FPGA クロッキング向け汎用 PLL として個別に設定することができます。Si5348 は、Stratum 3/3E 準拠を必要とするレガシ SETS システムでも使用できます。オプションのデジタル制御された発振器 (DCO) モードでは、1588 (PTP) クロック・ステアリング・アプリケーションで 1 ppt の正確なタイミング調整を行うことができます。Si5348 のユニークな設計により、TCXO/OCXO 基準入力によってデバイスの周波数確度と安定性が決まります。Si5348 は、回路内でプログラム可能な不揮発性メモリを備えたシリアル・インターフェイスを介してプログラム可能であるため、常に既知の構成で電源が投入されます。Si5348 は、ClockBuilder Pro™ ソフトウェアを使用して簡単にプログラムできます。工場出荷時にプログラムされているデバイスを使用することもできます。

アプリケーション：

- 同期イーサネット (SyncE) ITU-T G.8262 EEC オプション 1 & 2
- ITU-T G.8273.2 の定義によるテレコム・バウンダリ・クロック (T-BC)
- IEEE 1588 (PTP) スレーブ・クロック同期
- Stratum 3/3E、G.812、G.813 ネットワーク同期

主な機能

- 柔軟な SyncE/IEEE 1588 および SETS アーキテクチャに対応する単一のモノリシック IC の 3 つの独立した DSPLL
- 95 fs の超低ジッタ
- 出力位相トランジェントを最小限に抑える、強化されたヒットレス・スイッチング
- 入力周波数帯域：
  - 外部水晶：48 ～ 54 MHz
  - 基準 クロック：5 ～ 250 MHz
  - 差動クロック：8 kHz ～ 750 MHz
  - LVCMOS クロック：8 kHz ～ 250 MHz
- 出力周波数帯域：
  - 差動：1 PPS ～ 718.5 MHz
  - LVCMOS：1 PPS ～ 250 MHz
- 以下の要件に適合しています。
  - ITU-T G.8262 (SyncE) EEC オプション 1 および 2
  - ITU-T G.812 Type III、IV
  - ITU-T G.813 オプション 1
  - Telcordia GR-1244、GR-253 (Stratum-3/3E)



第 1 章 機能リスト

Si5348 の機能は次のとおりです。

- 柔軟な SyncE/IEEE 1588 および SETS アーキテクチャに対応する単一のモノリシック IC の 3 つの独立した DSPLL
- 超低ジッタ
  - 95 fs typ (12 kHz ～ 20 MHz)
- 以下の要件に適合しています。
  - ITU-T G.8273.2 T-BC
  - ITU-T G.8262 (SyncE) EEC オプション 1 & 2
  - ITU-T G.812 Type III、IV
  - ITU-T G.813 オプション 1
  - Telcordia GR-1244、GR-253 (Stratum-3/3E)
- 各 DSPLL によって任意の入力周波数で任意の出力周波数を生成
- 入力周波数帯域：
  - 外部水晶：48 ～ 54 MHz
  - 基準 クロック：5 ～ 250 MHz
  - 差動クロック：8 kHz ～ 750 MHz
  - LVCMOS クロック：8 kHz ～ 250 MHz
- 出力周波数帯域：
  - 差動：1 PPS ～ 718.5 MHz
  - LVCMOS：1 PPS ～ 250 MHz
- 各 DSPLL で独立した周波数オンザフライ
- 8 kHz、19.44 MHz、25 MHz、およびその他の入力周波数に対応し、出力位相トランジェントを最小限に抑える、強化されたヒットレス・スイッチング
- 1 ppt/step への標準的な分解能によって各 DSPLL でピンまたはソフトウェアによって制御可能な DCO
- TCXO/OCXO 基準入力によって、DSPLL フリーラン/ホールドオーバー精度および安定度が決定
- DSPLL 1 つ当たりのプログラム可能なジッタ減衰帯域幅：0.001 Hz ～ 4 kHz
- 高度に設定可能な出力ドライバ：LVDS、LVPECL、LVCMOS、HCSL、CML
- コア電圧：
  - VDD：1.8 V ±5%
  - VDDA：3.3 V ±5%
- 独立した出力電源ピン：3.3 V、2.5 V、または 1.8 V
- 内蔵電源フィルタリング
- ステータス監視：LOS、OOF、LOL
- シリアル・インターフェイス：I^2C または SPI (3 ワイヤまたは 4 ワイヤ)
- ClockBuilder Pro ソフトウェアでデバイス構成を簡素化
- 5 入力、7 出力、64 QFN
- 温度範囲：-40 ～ +85 °C
- 鉛フリー対応、RoHS-6 準拠

2. Related Documents

Table 2.1. Related Documentation and Software

Document/Resource	Description/URL
Si5348 Rev E Family Reference Manual	To be used in conjunction with this data sheet, which contains more detailed explanations about the operation of the device. http://www.silabs.com/documents/public/reference-manuals/si5348-e-family.pdf
Crystal Reference Manual	https://www.silabs.com/documents/public/reference-manuals/si534x-8x-recommended-crystals-rm.pdf
Frequently Asked Questions	https://www.silabs.com/community/timing/knowledge-base.entry
Quality and Reliability	http://www.silabs.com/quality
Development Kits	https://www.silabs.com/products/development-tools/timing/clock#highperformance
ClockBuilder Pro (CBPro) Software	https://www.silabs.com/products/development-tools/software/clockbuilder-pro-software
AN1077: Selecting the Right Clocks for Timing Synchronization Applications	https://www.silabs.com/documents/public/application-notes/an1077-selecting-clocks-for-timing-synchronization.pdf
UG123: SiOCXO1-EVB Evaluation Board Users Guide	https://www.silabs.com/documents/public/user-guides/UG123.pdf
UG362: Si5348 EVB User Guide	https://www.silabs.com/documents/public/user-guides/ug362-si5348-e-evb.pdf
UG364: SiTCXO1-EVB Evaluation Board User's Guide	https://www.silabs.com/documents/public/user-guides/ug364-sitcxo1-evb-ug.pdf
AN1170: Holdover Consideration for Si5348 Network Synchronizer Clocks	https://www.silabs.com/documents/public/application-notes/an1170-si5348-holdover-considerations.pdf
AN1173: Si5348 Rev D to Rev E Changes	https://www.silabs.com/documents/public/application-notes/an1173-si5348-revd-to-reve-changes.pdf

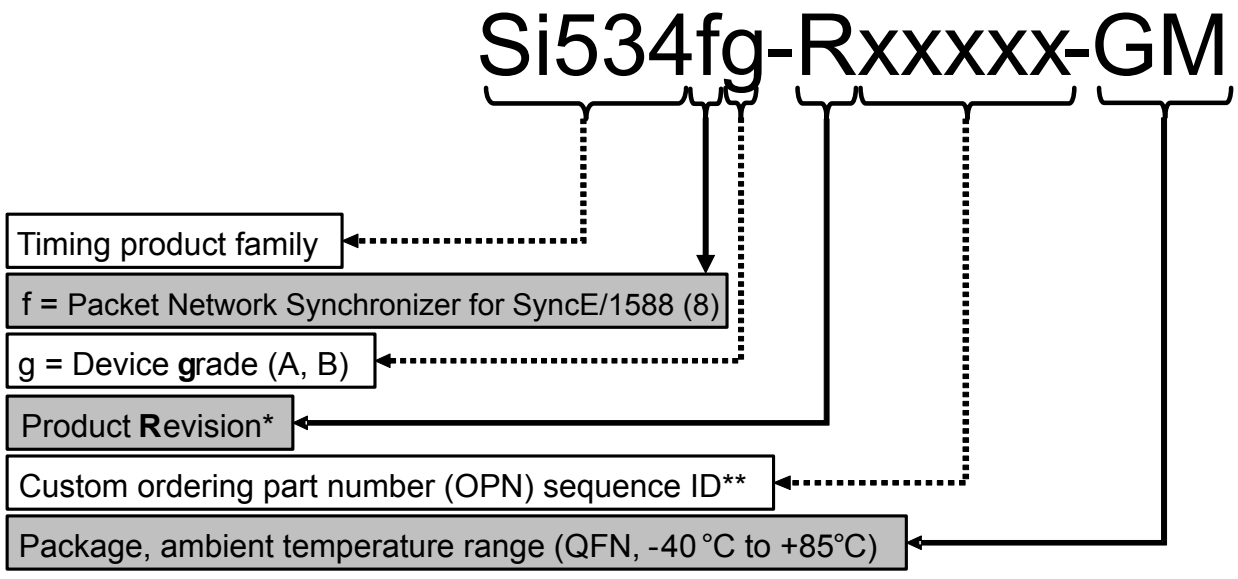
3. Ordering Guide

Table 3.1. Si5348 Ordering Guide

Ordering Part Number	# of DSPLLs	Output Clock Frequency Range	Package	RoHS-6 Pb-Free	Temperature Range
Si5348A-E-GM [1, 2]	3	1 Hz to 718.5 MHz	64-Lead 9x9 QFN	Yes	–40 to 85 °C
Si5348B-E-GM [1, 2]		1 Hz to 350 MHz			
Si5348-E-EVB	—	—	Evaluation Board	—	—
SiOCXO1-EVB	—	12.800 MHz	OCXO Evaluation Board	—	—
SiTCXO1-EVB	—	40 MHz	TCXO Evaluation Board	—	—

Note:

1. Add an "R" at the end of the device part number to denote tape and reel ordering options.
2. Custom, factory pre-programmed devices are available. Ordering part numbers are assigned by the ClockBuilder Pro software. Part number format is: Si5348A-Dxxxxx-GM, where “xxxxx” is a unique numerical sequence representing the pre-programmed configuration.



*See Ordering Guide table for current product revision
** 5 digits; assigned by ClockBuilder Pro

Figure 3.1. Ordering Part Number Fields

Table of Contents

4. Functional Description

The Si5348 offers three DSPLLs that can be independently configured and controlled through the serial interface. Each of the DSPLLs support locked, free-run, and holdover modes of operation with an optional DCO mode for IEEE 1588 applications. The device requires an external crystal and an external reference (TCXO or OCXO) to operate. The reference input (REF/REFb) determines the frequency accuracy and stability while in free-run and holdover modes. The external crystal completes the internal oscillator circuit (OSC) which is used by the DSPLL for intrinsic jitter performance. There are three main inputs (IN0 - IN2) for synchronizing the DSPLLs. Input selection can be manual or automatically controlled using an internal state machine. Two additional manually selected inputs are available to DSPLL D. Any of the output clocks (OUT0 to OUT6) can be configured to any of the DSPLLs using a flexible crosspoint connection. Output 6 is the only output that can be configured for a 1 Hz output to support 1 PPS.

4.1 Standards Compliance

Each of the DSPLLs meet the requirements of ITU-T G.8262 (SyncE), G.812, G.813, G.8273.2 (T-BC), in addition to Telcordia GR-1244 and GR-253 as shown in the compliance report. The DCO feature enables IEEE1588 (PTP) implementations in addition to hybrid SyncE + IEEE1588 (T-BC). The following table lists the Si5348 compliance reports for these standards.

Table 4.1. Si5348 Standards Compliance Reports

Standard	Compliance Report
G.8262 (SyncE)	http://www.silabs.com/documents/public/miscellaneous/si5348-rev-e-itu-t-g8262-compliance-report.pdf
G.812	https://www.silabs.com/documents/public/miscellaneous/Si5348_ITU-T_G.812_ComplianceTestResults_Rev1.0.pdf
G.813	https://www.silabs.com/documents/public/miscellaneous/Si5348_ITU-T_G.813_ComplianceTestResults_Rev1.0.pdf
GR-1244	https://www.silabs.com/documents/public/miscellaneous/Si5348_Telcordia_GR-1244_ComplianceTestResults_Rev1.0.pdf
GR-253	https://www.silabs.com/documents/public/miscellaneous/Si5348_Telcordia_GR-253_ComplianceTestResults_Rev1.0.pdf

4.2 Frequency Configuration

The frequency configuration for each of the DSPLLs is programmable through the serial interface and can also be stored in non-volatile memory. The combination of fractional input dividers (Pn/Pd), fractional frequency multiplication (Mn/Md), and integer output division (Rn) allows each of the DSPLLs to lock to any input frequency and generate virtually any output frequency. All divider values for a specific frequency plan are easily determined using the ClockBuilder Pro software. Each PLL can be reconfigured during operation without affecting the others. See 4.4.6 Frequency on the Fly for more information.

4.3 DSPLL Loop Bandwidth

The DSPLL loop bandwidth determines the amount of input clock jitter and wander attenuation. Register configurable DSPLL loop bandwidth settings of 1 mHz to 4 kHz are available for selection for each of the DSPLLs. Since the loop bandwidth is controlled digitally, each of the DSPLLs will always remain stable with less than 0.1 dB of peaking regardless of the loop bandwidth selection.

Table 4.2. Loop Bandwidth Requirements for North America

SONET (Telcordia)	SDH (ITU-T)	SyncE (ITU-T)	Loop Bandwidth
GR-253 Stratum 3E	G.812 Type III	—	0.001 Hz
GR-253 Stratum 3	G.812 Type IV	G.8262 EEC Option 2	<0.1 Hz
—	G.813 Option 1	G.8262 EEC Option 1	1 - 10 Hz

4.3.1 Fastlock Feature

Selecting a low DSPLL loop bandwidth (e.g. 0.1 Hz) will generally lengthen the lock acquisition time. The fastlock feature allows setting a temporary Fastlock Loop Bandwidth that is used during the lock acquisition process. Higher fastlock loop bandwidth settings will enable the DSPLLs to lock faster. Fastlock Loop Bandwidth settings in the range of 100 Hz to 4 kHz are available for selection. Once lock acquisition has completed, the DSPLL's loop bandwidth will automatically revert to the nominal DSPLL Loop Bandwidth setting. The fastlock feature can be enabled or disabled independently for each of the DSPLLs.

4.4 Modes of Operation

Once initialization is complete, each of the DSPLLs operates independently in one of four modes: Free-run Mode, Lock Acquisition Mode, Locked Mode, or Holdover Mode. A state diagram showing the modes of operation is shown in the figure below. The following sections describe each of these modes in greater detail.

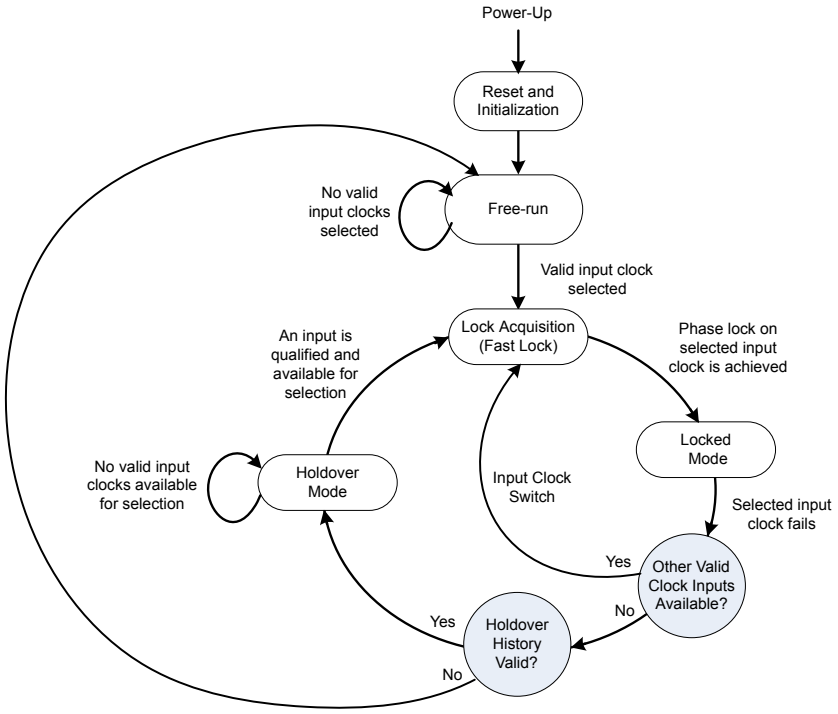


Figure 4.1. Modes of Operation

4.4.1 Initialization and Reset

Once power is applied, the device begins an initialization period where it downloads default register values and configuration data from NVM and performs other initialization tasks. Communicating with the device through the serial interface is possible once this initialization period is complete. No clocks will be generated until the initialization is complete. There are two types of resets available. A hard reset is functionally similar to a device power-up. All registers will be restored to the values stored in NVM, and all circuits will be restored to their initial state including the serial interface. A hard reset is initiated using the RSTb pin or by asserting the hard reset bit. A soft reset bypasses the NVM download. It is simply used to initiate register configuration changes. A hard reset affects all DSPLLs, while a soft reset can either affect all or each DSPLL individually.

4.4.2 Free-run Mode

Once power is applied to the Si5348 and initialization is complete, all three DSPLLs will automatically enter freerun mode. The frequency accuracy of the generated output clocks in freerun mode is entirely dependent on the frequency accuracy of the clock source at the reference inputs (REF/REFb). A TCXO or OCXO is recommended for applications that need frequency accuracy and stability to meet the synchronization standards as shown in the following table:

Table 4.3. Free-run Accuracy for North American and European Synchronization Standards

SONET (Telcordia)	SDH (ITU-T)	SyncE (ITU-T)	Free-run Accuracy
GR-253 Stratum 3E	G.812 Type III	—	±4.6 ppm
GR-253 Stratum 3	G.812 Type IV	G.8262 EEC Option 2	
—	G.813 Option 1	G.8262 EEC Option 1	

4.4.3 Lock Acquisition Mode

Each of the DSPLLs independently monitors its configured inputs for a valid clock. If at least one valid clock is available for synchronization, a DSPLL will automatically start the lock acquisition process.If the fast lock feature is enabled, a DSPLL will acquire lock using the Fastlock Loop Bandwidth setting and then transition to the DSPLL Loop Bandwidth setting when lock acquisition is complete. During lock acquisition the outputs will generate a clock that follows the VCO frequency change as it pulls-in to the input clock frequency.

4.4.4 Locked Mode

Once locked, a DSPLL will generate output clocks that are both frequency and phase locked to their selected input clocks. At this point, any XTAL frequency drift will not affect the output frequency. Each DSPLL has its own LOLb pin and status bit to indicate when lock is achieved. Refer to 4.8.6 LOL Detection for more details on the operation of the loss of lock circuit.

4.4.5 Holdover Mode

Any of the DSPLLs will automatically enter Holdover Mode when the selected input clock becomes invalid and no other valid input clocks are available for selection. Each DSPLL uses an averaged input clock frequency as its final holdover frequency to minimize the disturbance of the output clock phase and frequency when an input clock suddenly fails. The holdover circuit for each DSPLL stores up to 120 seconds of historical frequency data while locked to a valid clock input. The final averaged holdover frequency value is calculated from a programmable window within the stored historical frequency data. Both the window size and delay are programmable as shown in the figure below. The window size determines the amount of holdover frequency averaging. The delay value allows ignoring frequency data that may be corrupt just before the input clock failure.

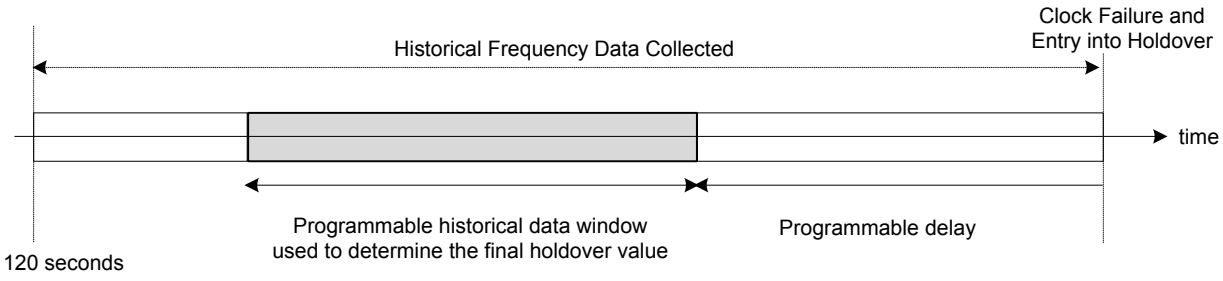


Figure 4.2. Programmable Holdover Window

When entering holdover, a DSPLL will pull its output clock frequency to the calculated averaged holdover frequency. While in holdover, the output frequency drift is entirely dependent on the external reference clock connected to the REF/REFb pins. If the clock input becomes valid, a DSPLL will automatically exit the holdover mode and re-acquire lock to the new input clock. This process involves pulling the output clock frequencies to achieve frequency and phase lock with the input clock. This pull-in process is glitchless.

The DSPLL output frequency when exiting holdover can be ramped (recommended). Just before the exit is initiated, the difference between the current holdover frequency and the new desired frequency is measured. Using the calculated difference and a user-selectable ramp rate, the output is linearly ramped to the new frequency. The ramp rate can be 0.2 ppm/s, 40,000 ppm/s, or any of about 40 values in between. The DSPLL loop BW does not limit or affect ramp rate selections (and vice versa). CBPro defaults to ramped exit from holdover. The same ramp rate settings are used for both exit from holdover and ramped input switching. For more information on ramped input switching see 4.7.6 Ramped Input Switching.

Note: If ramped holdover exit is not selected, the holdover exit is governed either by (1) the DSPLL loop BW or (2) a user-selectable holdover exit BW.

4.4.6 Frequency on the Fly

The Si5348 Rev E uses register writes to support configuration on the fly to allow certain characteristics to be changed on one DSPLL without affecting the clocks generated from other DSPLLs. These characteristics include Input/Output Frequencies, PLL bandwidth, LOL, and OOF settings. This feature is limited to DSPLLs A, C, and D and can only be used on DSPLLs that do not share a common input with other DSPLLs. See the Si5348 Rev E Reference Manual for more details.

4.5 Digitally-Controlled Oscillator (DCO) Mode

The DSPLLs support a DCO mode where their output frequencies are adjustable in pre-defined steps defined by frequency step words (FSW). The frequency adjustments are controlled through the serial interface or by pin control using frequency increments (FINC) or decrements (FDEC). A FINC will add the frequency step word to the DSPLL output frequency, while a FDEC will decrement it. The DCO mode is available when the DSPLL is operating in locked mode. The DCO mode is mainly used in IEEE1588 (PTP) applications where a clock needs to be generated based on recovered timestamps. In this case timestamps are recovered by the PHY/MAC. A processor containing servo software controls the DCO to close the timing loop between the master and slave nodes. The processor has the option of using the FINC/FDEC pin controls to update the DCO frequency or by controlling it through the serial interface.

4.6 External Reference (XA/XB, REF/REFb)

The external crystal at the XA/XB pins determines jitter performance of the output clocks, and the external reference clock at the REF/REFb pins determines the frequency accuracy, wander and stability during free-run or holdover modes. Jitter from the external clock on the REF/REFb pins will have little effect on the output jitter performance, depending upon the selected bandwidth.

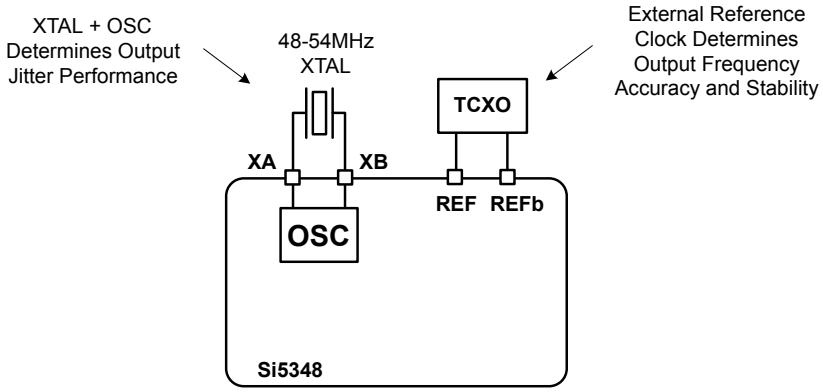


Figure 4.3. External Reference Connections

Note: XA, XB, REF, and REFb must not exceed the maximum input voltage listed in Table 6.3 Input Clock Specifications on page 26.

4.6.1 External Crystal (XA/XB)

The external crystal (XTAL) is used in combination with the internal oscillator (OSC) to produce an ultra low jitter reference clock for the DSPLLs. The device includes internal XTAL loading capacitors which eliminate the need for external capacitors and also has the benefit of reduced noise coupling from external sources. A crystal in the range of 48 to 54 MHz is recommended for best jitter performance. Although the device includes built-in XTAL load capacitors (CL) of 8 pF, crystals with load capacitances up to 18 pF can also be accommodated. The Si5348 Rev E Reference Manual provides additional information on PCB layout recommendations for the crystal to ensure optimum jitter performance. Although ***not*** recommended, the device can also accommodate an external clock at the XA/XB pins instead of a crystal. Selection between the external crystal or clock is controlled by register configuration. The internal crystal loading capacitors (CL) are disabled in this mode. Refer to Table 6.12 Crystal Specifications[1] on page 37 for reference clock requirements when using this mode. The Si5348 Rev E Reference Manual provides additional information on PCB layout recommendations for the crystal to ensure optimum jitter performance.

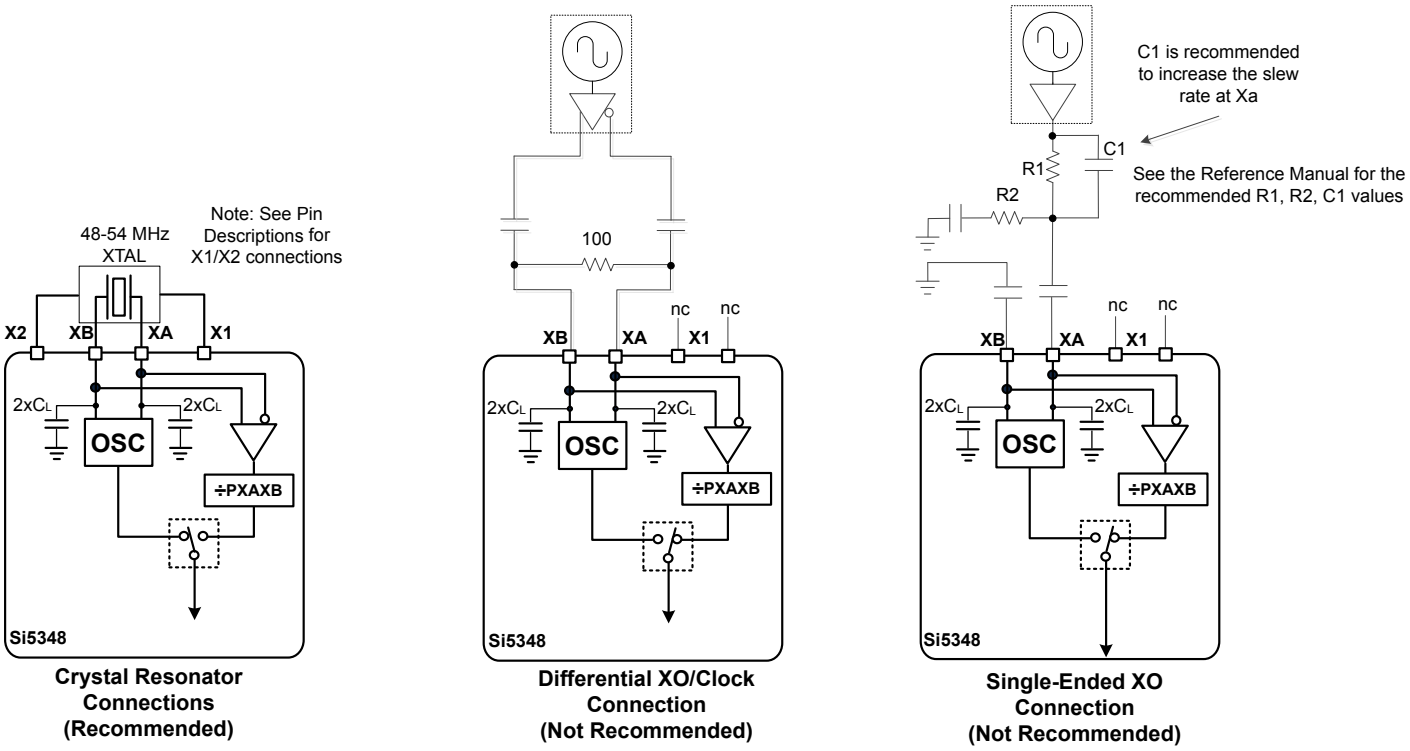


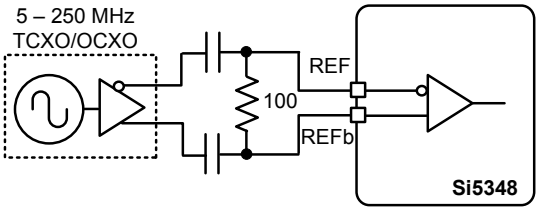
Figure 4.4. Crystal Resonator Connections

Note: XA and XB must not exceed the maximum input voltage listed in Table 6.3 Input Clock Specifications on page 26.

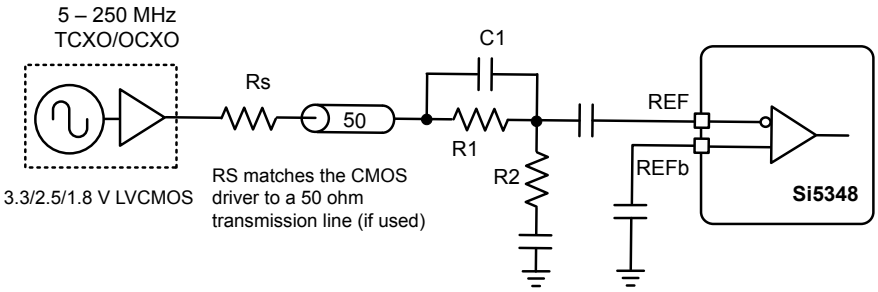
4.6.2 External Reference (REF/REFb)

The external reference at the REF/REFb pins is used to determine output frequency accuracy and stability during free-run and holdover modes. This reference is usually from a TCXO or OCXO and can be connected differentially or single-ended as shown in the figure below. See the Si5348 Rev E Reference Manual and the Si534x/8x Recommended Crystal, TCXO and OCXOs Reference Manual for more information.

Differential Reference Connection



Single-Ended AC-Coupled Reference Connections



Use R1 and R2 if necessary to keep the signal at REF < 3.6 Vpp_se.
See Reference Manual for details.

Figure 4.5. External Reference Connections

Note: REF and REFb must not exceed the maximum input voltage listed in Table 6.3 Input Clock Specifications on page 26.

4.7 Inputs (IN0, IN1, IN2, REF, IN3, IN4)

There are four inputs that can be used to synchronize DSPLLs A, C and six inputs for DSPLL D. The inputs accept both differential and single-ended clocks. A crosspoint between the inputs and the DSPLLs allows any of the inputs (IN0, IN1, IN2, REF) to be connected to DSPLLA, DSPLLC or DSPLLD as shown in the figure below. DSPLL D has two additional inputs (IN3 and IN4) that support the single-ended LVCMOS input format only. Refer to the Si5348 Rev E Reference Manual for details.

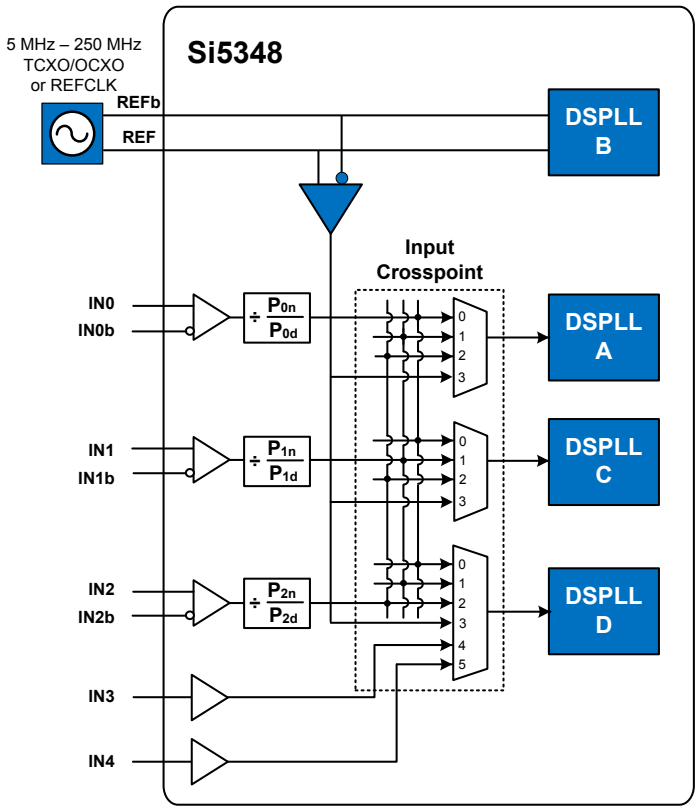


Figure 4.6. DSPLL Input Selection Crosspoint

4.7.1 Input Selection

Input selection for each of the DSPLLs can be made manually through register control or automatically using an internal state machine when fewer than five inputs are used.

4.7.2 Manual Input Selection

In manual mode the input selection is made by writing to a register. IN0-IN2 and REF is available to DSPLL A and C, IN0-IN4 and REF is available to DSPLL D. If there is no clock signal on the selected input, the DSPLL will automatically enter holdover mode.

4.7.3 Automatic Input Selection

When configured in this mode, the DSPLLs automatically select a valid input that has the highest configured priority. The priority scheme is independently configurable for each DSPLL and supports revertive or non-revertive selection. Refer to the Si5348 Rev E Reference Manual for details.

4.7.4 Input Configuration and Terminations

Each of the differential inputs IN0–IN2, and REF are compatible with standard LVDS, LVPECL, HCSL, CML, and single-ended LVCMOS formats, or as a low duty cycle pulsed CMOS format. The standard format inputs have a nominal 50% duty cycle, must be ac-coupled and use the “Standard” Input Buffer selection as these pins are internally dc-biased to approximately 0.83 V. The pulsed CMOS input format allows pulse-based inputs, such as frame-sync and other synchronization signals having a duty cycle much less than 50%. These pulsed CMOS signals are dc-coupled and use the “Pulsed CMOS” Input Buffer selection. In all cases, the inputs should be terminated near the device input pins as shown in the figure below. The resistor divider values given below will work with up to 1 MHz pulsed inputs. In general, following the “Standard AC Coupled Single Ended” arrangement shown below will give superior jitter performance. Inputs must not exceed the maximum input voltages listed in Table 6.3 Input Clock Specifications on page 26. See Section 5.2 of the Si5348 Rev E Reference Manual for input circuit recommendations.

4.7.5 Hitless Input Switching

Hitless switching is a feature that prevents a phase offset from propagating to the output when switching between two clock inputs that have a fixed phase relationship. A hitless switch can only occur when the two input frequencies are frequency locked, meaning that they have to be exactly at the same frequency, or at an integer frequency relationship to each other. When hitless switching is enabled, the DSPLL simply absorbs the phase difference between the two input clocks during an input switch. When disabled, the phase difference between the two inputs is propagated to the output at a rate determined by the DSPLL Loop Bandwidth. The hitless switching feature supports clock frequencies down to the minimum input frequency of 8 kHz. Hitless switching can be enabled on a per DSPLL basis.

4.7.6 Ramped Input Switching

The ramped input switching feature is enabled/disabled depending on both the Pfd frequency and difference in input frequencies (Zero-PPM vs non-zero PPM). The table below shows the selection criteria to enable ramped input switching. The same ramp rate settings are used for both holdover exit and clock switching. For more information on ramped exit from holdover, see 4.4.5 Holdover Mode and the Si5348 Rev E Reference Manual.

Table 4.4. Recommended Ramped Input Switching Settings for Internal Clock Switches

Maximum Input Frequency Difference	Fpfd < 500 kHz	Fpfd ≥ 500 kHz
0 ppm Frequency Locked	Ramped Exit from Holdover	
≤ 10 ppm	Ramped Input Switching and Ramped Exit from Holdover	Ramped Exit from Holdover
> 10 ppm	Ramped Input Switching and Ramped Exit from Holdover	

4.7.7 Glitchless Input Switching

The DSPLLs have the ability of switching between two input clock frequencies that are up to ±500 ppm apart. The DSPLL will pull-in to the new frequency using the DSPLL Loop Bandwidth or using the Fastlock Loop Bandwidth if it is enabled. The loss of lock (LOL) indicator will assert while the DSPLL is pulling-in to the new clock frequency. There will be no output runt pulses generated at the output during the transition. All clock inputs, including IN3 and IN4, support glitchless input switching.

4.7.8 Typical Hitless Switching Scenarios

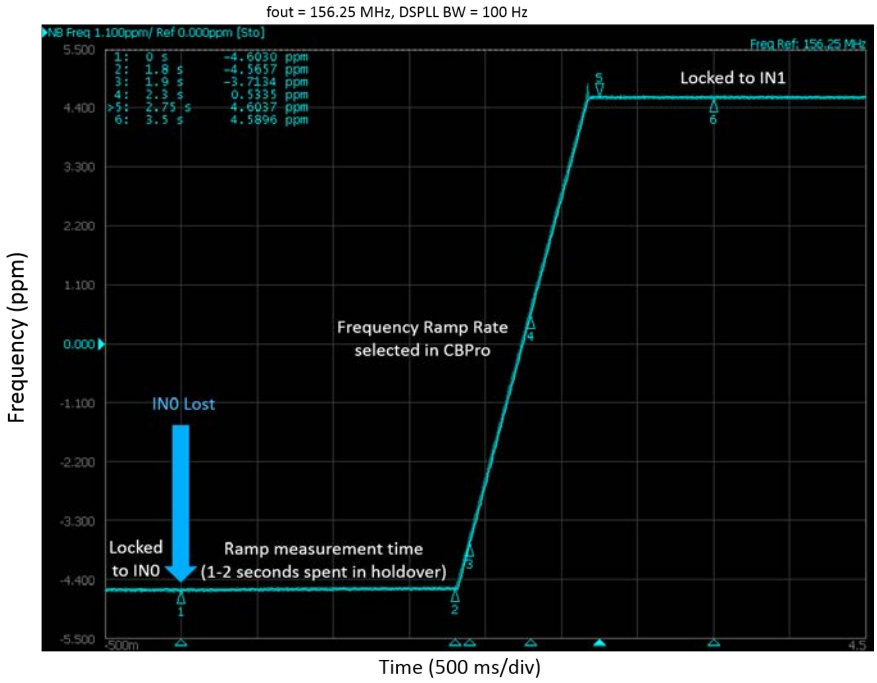


Figure 4.7. Output Frequency Transient—Ramped Switching between Two 8 kHz Inputs (±4.6 ppm Offset)

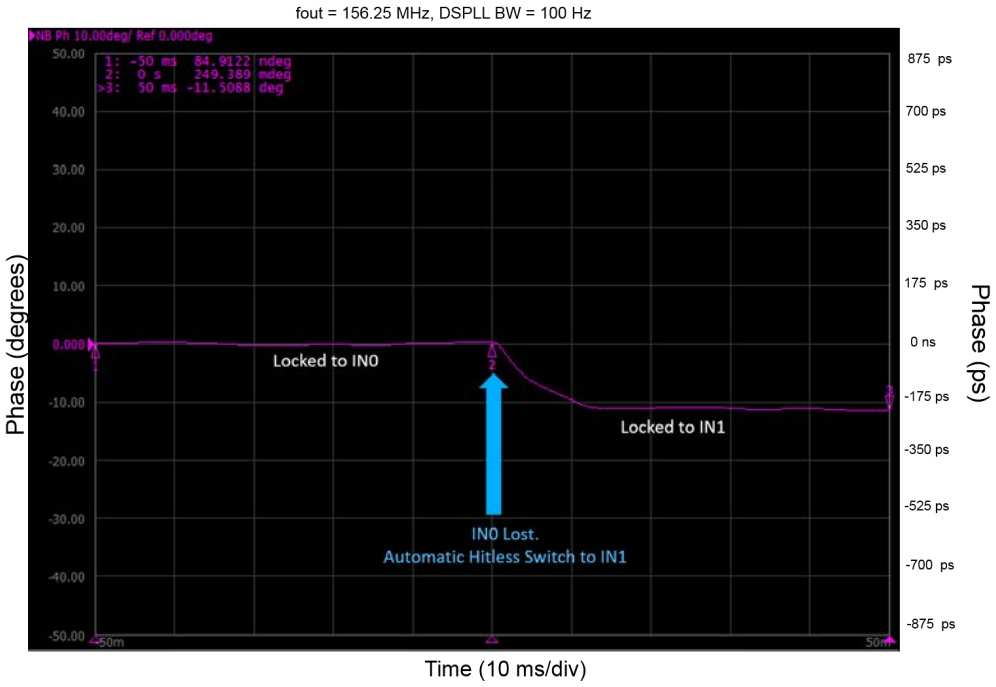


Figure 4.8. Output Phase Transient—Hitless Switching between Two 25 MHz Inputs (0 ppm, 180 Degree Phase Shift)

4.7.9 Synchronizing to Gapped Input Clocks

Each of the DSPLLs support locking to an input clock that has missing periods. This is also referred to as a gapped clock. The purpose of gapped clocking is to modulate the frequency of a periodic clock by selectively removing some of its cycles. Gapping a clock severely increases its jitter, so a phase-locked loop with high jitter tolerance and low loop bandwidth is required to produce a low-jitter periodic clock. The resulting output will be a periodic non-gapped clock with an average frequency of the input with its missing cycles. For example, an input clock of 100 MHz with one cycle removed every 10 cycles will result in a 90 MHz periodic non-gapped output clock. This is shown in the figure below:

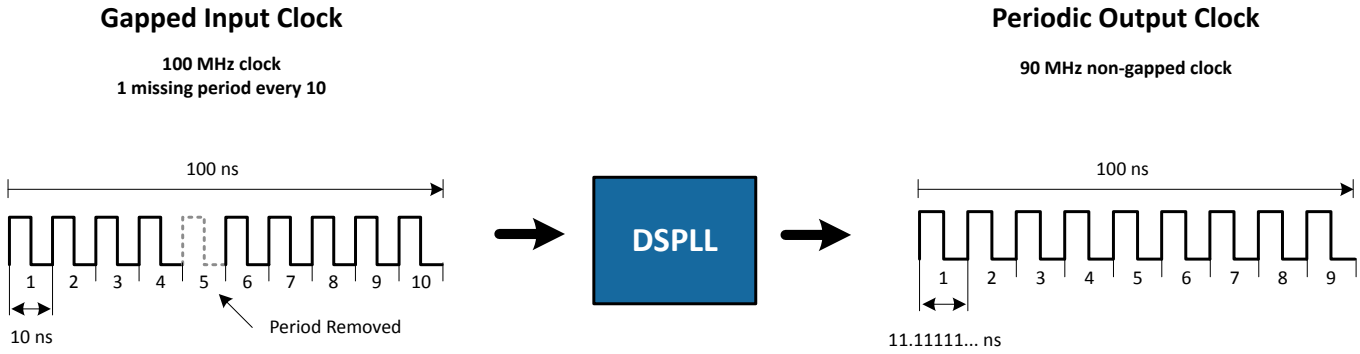


Figure 4.9. Generating an Averaged Clock Output Frequency from a Gapped Clock Input

A valid gapped clock input must have a minimum frequency of 10 MHz with a maximum of two missing cycles out of every eight. Locking to a gapped clock will not trigger the LOS, OOF, and LOL fault monitors. Clock switching between gapped clocks may violate the hitless switching specification in Table 6.8 Performance Characteristics on page 32 when the switch occurs during a gap in either input clock.

4.8 Fault Monitoring

Three input clocks (IN0, IN1, IN2) and the reference input (REF/REFb) are monitored for loss-of-signal (LOS) and out-of-frequency (OOF) as shown in the figure below. The reference at the XA/XB pins is also monitored for LOS since it provides a critical reference clock for the DSPLLs. Each of the DSPLLs also has an LOL indicator, which is asserted when synchronization is lost with their selected input clock. IN3 and IN4 can be monitored, only for LOS, on DSPLL D.

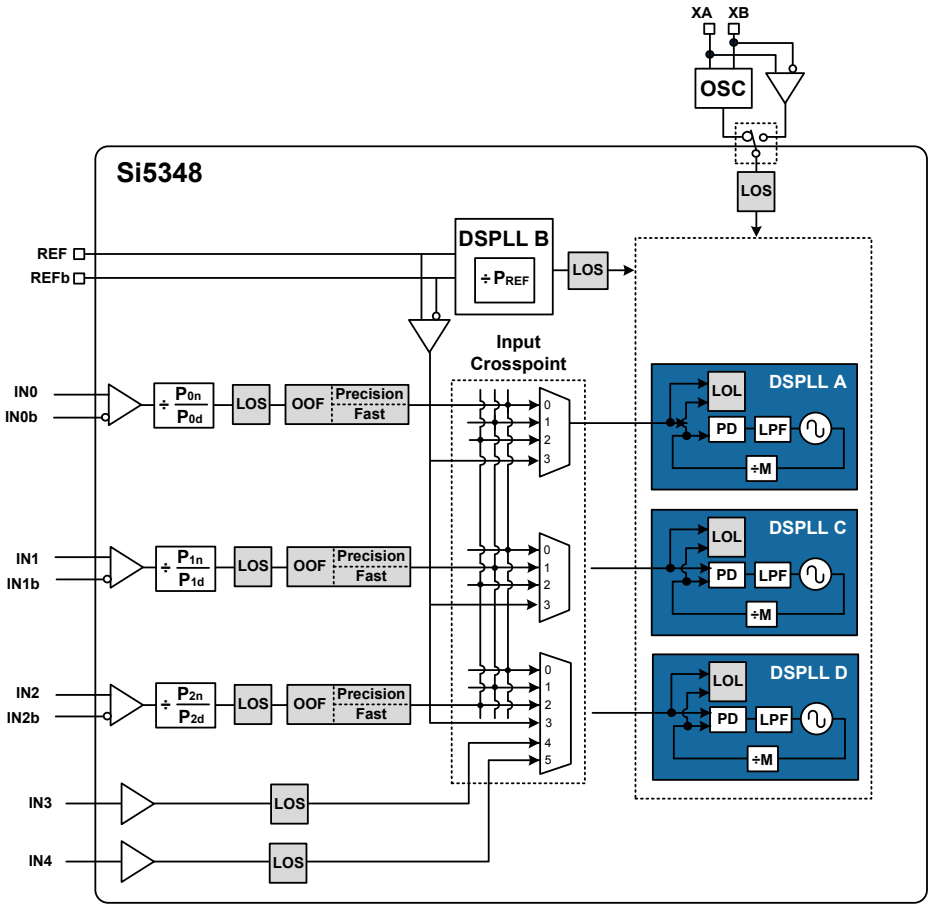


Figure 4.10. Si5348 Fault Monitors

4.8.1 Input LOS Detection

The loss of signal monitor measures the period of each input clock cycle to detect phase irregularities or missing clock edges. Each of the input LOS circuits has its own programmable sensitivity which allows ignoring missing edges or intermittent errors. Loss of signal sensitivity is configurable using the ClockBuilder Pro software. Refer to the Si5348 Rev E Reference Manual for details.

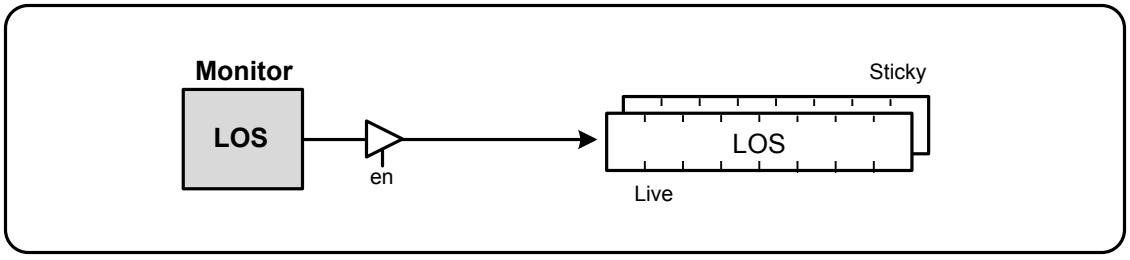


Figure 4.11. LOS Status Indicators

4.8.2 XA/XB LOS Detection

A LOS monitor is available to ensure that the external crystal or reference clock is valid. By default the output clocks are disabled when XAXB_LOS is detected. This feature can be disabled such that the device will continue to produce output clocks when XAXB_LOS is detected.

4.8.3 OOF Detection

Input clocks IN0, IN1, IN2 are monitored for frequency accuracy with respect to an OOF reference, which it considers as its “0_ppm” reference. Since a TCXO or OCXO will be connected to the REF input, most applications will declare the REF input to be the OOF reference. The final OOF status is determined by the combination of both a precise OOF monitor and a fast OOF monitor as shown in the figure below. An option to disable either monitor is also available. The live OOF register always displays the current OOF state and its sticky register bit stays asserted until cleared.

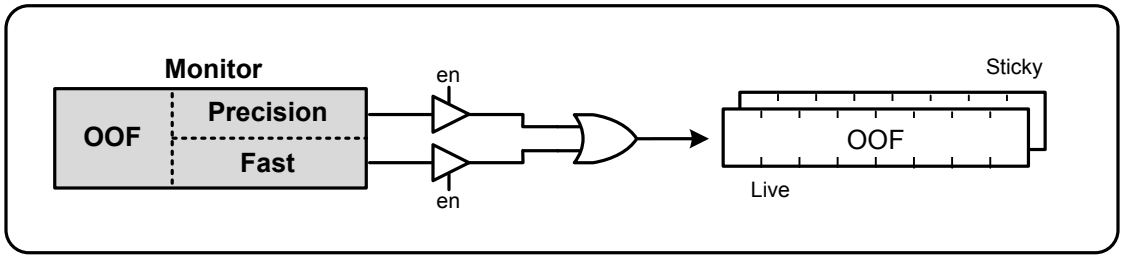


Figure 4.12. OOF Status Indicator

4.8.4 Precision OOF Monitor

The precision OOF monitor circuit measures the frequency of all input clocks to within ±1/16 ppm accuracy with respect to the selected OOF frequency reference. A valid input clock frequency is one that remains within the OOF frequency range, which is register configurable up to ±500 ppm in steps of 1/16 ppm. A configurable amount of hysteresis is also available to prevent the OOF status from toggling at the failure boundary. An example is shown in the figure below. In this case, the OOF monitor is configured with a valid frequency range of ±6 ppm and with 2 ppm of hysteresis. An option to use one of the input pins (IN0 – IN2) as the 0 ppm OOF reference instead of the REF/REFb pins is available. This option is register-configurable. XA/XB can also be used as the 0 ppm reference.

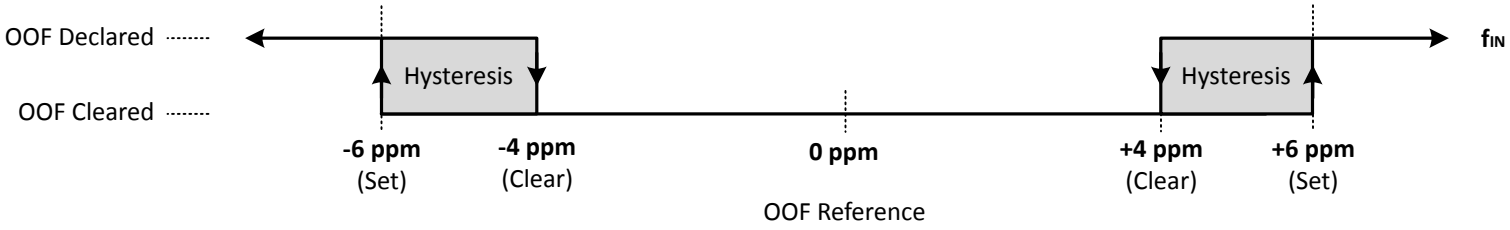


Figure 4.13. Example of Precise OOF Monitor Assertion and De-assertion Triggers

4.8.5 Fast OOF Monitor

Because the precision OOF monitor needs to provide 1/16 ppm of frequency measurement accuracy, it must measure the monitored input clock frequencies over a relatively long period of time. This may be too slow to detect an input clock that is quickly ramping in frequency. An additional level of OOF monitoring called the Fast OOF monitor runs in parallel with the precision OOF monitors to quickly detect a ramping input frequency. The Fast OOF monitor asserts OOF on an input clock frequency that has changed by greater than ±4000 ppm.

4.8.6 LOL Detection

There is an LOL monitor for each of the DSPLLs. The LOL monitor asserts the LOL register bit when a DSPLL has lost synchronization with its selected input clock. There is also a dedicated loss of lock pin that reflects the loss of lock condition for each of the DSPLLs (LOL_Ab, LOL_Cb, LOL_Db) and also for the reference. There are two LOL frequency monitors, one that sets the LOL indicator (LOL Set) and another that clears the indicator (LOL Clear). An optional timer is available to delay clearing of the LOL indicator to allow additional time for the DSPLL to completely lock to the input clock. The timer is also useful to prevent the LOL indicator from toggling or chattering as the DSPLL completes lock acquisition. A block diagram of the LOL monitor is shown in the figure below. The live LOL register always displays the current LOL state and a sticky register always stays asserted until cleared. The LOLb pin reflects the current state of the LOL monitor.

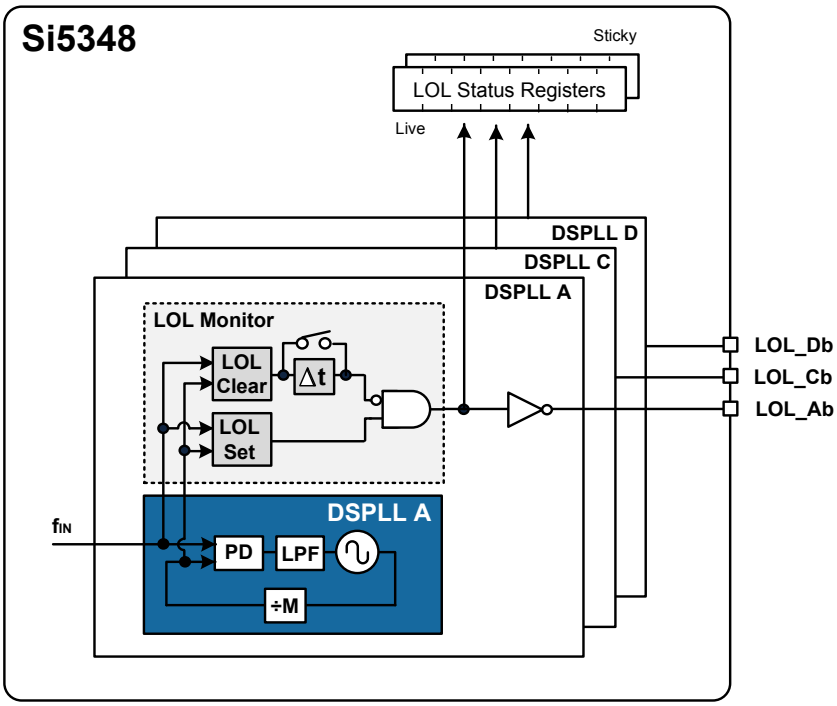


Figure 4.14. LOL Status Indicators

Each of the LOL frequency monitors has adjustable sensitivity, which is register-configurable from 0.1 ppm to 10,000 ppm. Having two separate frequency monitors allows for hysteresis to help prevent chattering of LOL status. An example configuration where LOCK is indicated when there is less than 0.1 ppm frequency difference at the inputs of the phase detector and LOL is indicated when there is more than 1 ppm frequency difference is shown in Figure 4.15 LOL Set and Clear Thresholds on page 19.

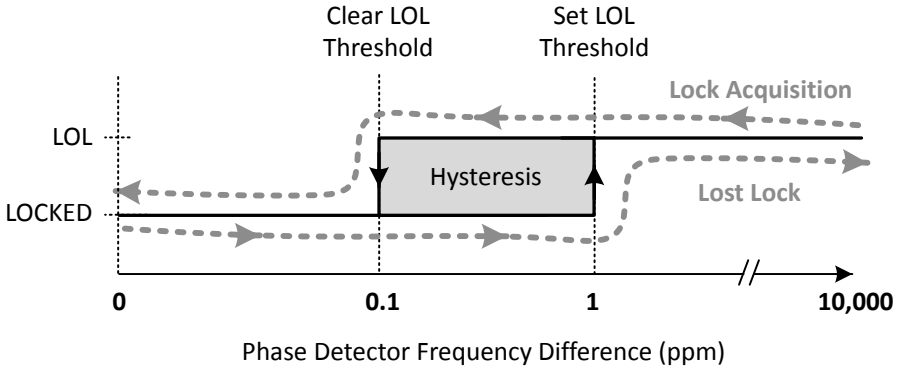


Figure 4.15. LOL Set and Clear Thresholds

An optional timer is available to delay clearing of the LOL indicator to allow additional time for the DSPLL to completely lock to the input clock. The timer is also useful to prevent the LOL indicator from toggling or chattering as the DSPLL completes lock acquisition. The

configurable delay value depends on frequency configuration and loop bandwidth of the DSPLL and is automatically calculated using the ClockBuilder Pro software.

4.8.7 Interrupt Pin (INTRb)

An interrupt pin (INTRb) indicates a change in state with any of the status indicators for any of the DSPLLs. All status indicators are maskable to prevent assertion of the interrupt pin. The state of the INTRb pin is reset by clearing the sticky status registers.

4.9 Outputs

The Si5348 supports seven differential output drivers. Each driver has a configurable voltage amplitude and common mode voltage covering a wide variety of differential signal formats including LVPECL, LVDS, HCSL, and CML. In addition to supporting differential signals, any of the outputs can be configured as single-ended LVCMOS (3.3 V, 2.5 V, or 1.8 V) providing up to 14 single-ended outputs, or a combination of differential and single-ended outputs.

4.9.1 Output Crosspoint

A crosspoint allows any of the output drivers to connect with any of the DSPLLs as shown in the figure below. The crosspoint configuration is programmable and can be stored in NVM so that the desired output configuration is ready at power-up.

4.9.2 Support For 1 Hz Output

Output 6 of the Si5348 can be configured to generate a 1 Hz clock by cascading the R5 and R6 dividers. Output 5 is still usable in this case but is limited to a maximum frequency of 33.5 MHz. ClockBuilder Pro automatically determines the optimum configuration when generating a 1 Hz output (1 PPS).

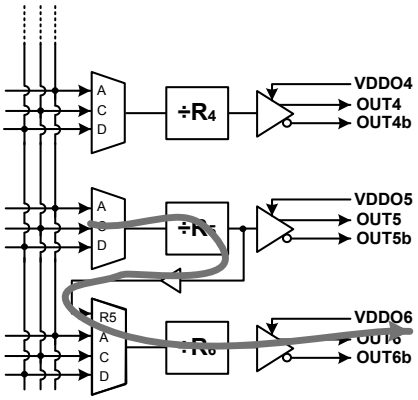


Figure 4.16. Generating a 1 Hz Output using the Si5348

4.9.3 Output Terminations

The outputs of the Si5348 can be configured in a variety of formats including: LVDS, LVCMOS, LVPECL, CML, and HCSL. For output termination circuit configuration recommendations, see the Si5348 Rev E Reference Manual.

4.9.4 Output Signal Format

The differential output amplitude and common mode voltage are both programmable and compatible with a wide variety of signal formats, including LVDS and LVPECL. In addition to supporting differential signals, any of the outputs can be configured as LVCMOS (3.3 V, 2.5 V, or 1.8 V) drivers providing up to 14 single-ended outputs or a combination of differential and single-ended outputs.

4.9.5 Programmable Common Mode Voltage For Differential Outputs

The common mode voltage (V_{CM}) for the differential modes is programmable and depends on the voltage available at the output's VDDO pin. Setting the common mode voltage is useful when dc-coupling the output drivers.

4.9.6 LVCMOS Output Impedance Selection

Each LVCMOS driver has a configurable output impedance to accommodate different trace impedances and drive strengths. A source termination resistor is recommended to help match the selected output impedance to the trace impedance. There are three programmable output impedance selections for each VDDO options as shown in the table below. Note that selecting a lower source impedance may result in higher output power consumption.

Table 4.5. Typical Output Impedance (Z_S)

VDDO	CMOS_DRIVE_Selection		
	OUTx_CMOS_DRV=1	OUTx_CMOS_DRV=2	OUTx_CMOS_DRV=3
3.3 V	38 Ω	30 Ω	22 Ω
2.5 V	43 Ω	35 Ω	24 Ω
1.8 V	—	46 Ω	31 Ω

4.9.7 LVCMOS Output Signal Swing

The signal swing (V_{OL}/V_{OH}) of the LVCMOS output drivers is set by the voltage on the VDDO pins. Each output driver has its own VDDO pin allowing a unique output voltage swing for each of the LVCMOS drivers.

4.9.8 LVCMOS Output Polarity

When a driver is configured as an LVCMOS output, it generates a clock signal on both pins (OUTx and OUTxb). By default the clock on the OUTxb pin is generated with the same polarity (in phase) with the clock on the OUTx pin. The polarity of these clocks is configurable, which enables complementary clock generation and/or inverted polarity with respect to other output drivers.

4.9.9 Output Enable/Disable

The Si5348 allows enabling/disabling outputs by pin or register control, or a combination of both. Three output enable pins are available (OE0b, OE1b, OE2b). The output enable pins can be mapped to any of the outputs (OUTx) through register configuration. By default OE0b controls all of the outputs while OE1b and OE2b remain unmapped and has no effect until configured. The figure below shows an example of an output enable mapping scheme that is register configurable and can be stored in NVM as the default at power-up.

Enabling and disabling outputs can also be controlled by register control. This allows disabling one or more output when the OEb pin(s) has them enabled. By default the output enable register settings are configured to allow the OEb pins to have full control.

4.9.10 Output Disable During LOL

By default a DSPLL that is out of lock will generate either free-running clocks or generate clocks in holdover mode. There is an option to disable the outputs when a DSPLL is LOL. This option can be useful to force a downstream PLL into holdover.

4.9.11 Output Disable During XAXB_LOS

The internal oscillator circuit (OSC) in combination with the external crystal (XTAL) provides a critical function for the operation of the DSPLLs. In the event of a crystal failure the device will assert an XAXB_LOS alarm. By default all outputs will be disabled during assertion of the XAXB_LOS alarm. There is an option to leave the outputs enabled during an XAXB_LOS alarm, but the frequency accuracy and stability will be indeterminate during this fault condition.

4.9.12 Output Driver State When Disabled

The disabled state of an output driver is register configurable as disable low or high.

4.9.13 Synchronous/Asynchronous Output Disable

Outputs can be configured to disable synchronously or asynchronously. In synchronous disable mode the output will wait until a clock period has completed before the driver is disabled. This prevents unwanted runt pulses from occurring when disabling an output. In asynchronous disable mode, the output clock will disable immediately without waiting for the period to complete.

4.9.14 Output Divider (R) Synchronization

All the output R dividers are reset to a known state during the power-up initialization period. This ensures consistent and repeatable phase alignment across all output drivers. Resetting the device using the RSTb pin or asserting the hard reset bit will have the same result.

4.10 Power Management

Unused inputs, output drivers, and DSPLLs can be powered down when unused.

4.11 In-Circuit Programming

The Si5348 is fully configurable using the serial interface (I^2C or SPI). At power-up the device downloads its default register values from internal non-volatile memory (NVM). Application specific default configurations can be written into NVM allowing the device to generate specific clock frequencies at power-up. Writing default values to NVM is in-circuit programmable with normal operating power supply voltages applied to its V_{DD} and V_{DDA} pins. The NVM is two time writable. Once a new configuration has been written to NVM, the old configuration is no longer accessible.

4.12 Serial Interface

Configuration and operation of the Si5348 is controlled by reading and writing registers using the I^2C or SPI interface. The I2C_SEL pin selects I^2C or SPI operation. Communication with both 3.3 V and 1.8 V host is supported. The SPI mode operates in either 4-wire or 3-wire mode.

4.13 Custom Factory Preprogrammed Parts

For applications where a serial interface is not available for programming the device, custom pre-programmed parts can be ordered with a specific configuration written into NVM. A factory pre-programmed part will generate clocks at power-up. Custom, factory-pre-programmed devices are available. Use the ClockBuilder Pro custom part number wizard to quickly and easily request and generate a custom part number for your configuration.

In less than three minutes, you will be able to generate a custom part number with a detailed data sheet addendum matching your design's configuration. Once you receive the confirmation email with the data sheet addendum, simply place an order with your local Silicon Labs sales representative. Samples of your pre-programmed device will typically ship in about two weeks.

5. Register Map

Refer to the Si5348 Rev E Reference Manual for a complete list of register descriptions and settings.

6. Electrical Specifications

Table 6.1. Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Ambient Temperature	T_A	–40	25	85	°C
Junction Temperature	TJ_{MAX}	—	—	125	°C
Core Supply Voltage	V_{DD}	1.71	1.80	1.89	V
	V_{DDA}	3.14	3.30	3.47	V
Output Driver Supply Voltage	V_{DDO}	3.14	3.30	3.47	V
		2.37	2.50	2.62	V
		1.71	1.80	1.89	V
Status Pin Supply Voltage	V_{DDS}	3.14	3.30	3.47	V
		1.71	1.80	1.89	V

Note:

1. All minimum and maximum specifications are guaranteed and apply across the recommended operating conditions. Typical values apply at nominal supply voltages and an operating temperature of 25 °C unless otherwise noted.

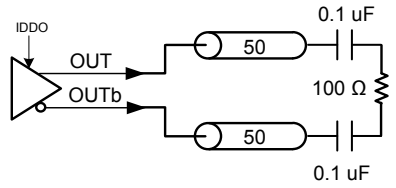
Table 6.2. DC Characteristics

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Core Supply Current[1]	I_{DD}		—	250	460	mA
	I_{DDA}		—	125	145	mA
Output Buffer Supply Current	I_{DDOx}	LVPECL Output[2] @ 156.25 MHz	—	22	26	mA
		LVDS Output[2] @ 156.25 MHz	—	15	18	mA
		3.3 V LVCMOS[3] output @ 156.25 MHz	—	22	30	mA
		2.5 V LVCMOS[3] output @ 156.25 MHz	—	18	23	mA
		1.8 V LVCMOS[3] output @ 156.25 MHz	—	12	16	mA
Total Power Dissipation[1, 4]	P_d	Si5348	—	1250	1650	mW

Note:

1. Si5348 test configuration: 7 x 2.5 V LVDS outputs enabled @156.25 MHz. Excludes power in termination resistors.
2. Differential outputs terminated into an ac-coupled 100 Ω split termination load. See the Si5348 Rev E Reference Manual for additional information.
3. LVCMOS outputs measured into a 5-inch 50 Ω PCB trace with 4.7 pF load. The LVCMOS outputs were set to OUTx_CMOS_DRV = 3, which is the strongest driver setting. Refer to the Si5348 Rev E Reference Manual for more details on register settings.
4. Detailed power consumption for any configuration can be estimated using the ClockBuilder Pro software when an evaluation board (EVB) is not available. All EVBs support detailed current measurements for any configuration.

Differential Output Test Configuration



LVCMOS Output Test Configuration

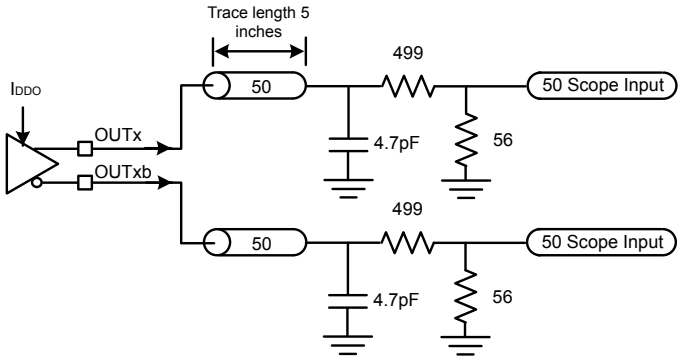


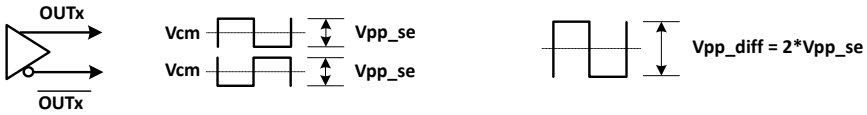
Table 6.3. Input Clock Specifications

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Standard Differential or Single-Ended AC-Coupled Input Buffer (IN0, IN1, IN2, REF)						
Input Frequency Range	f_{IN}	Differential	0.008	—	750	MHz
		Single-ended/LVCMOS	0.008	—	250	
		REF	5	—	250	
Voltage Swing [1]	V_{IN}	Differential AC-coupled f_{IN}< 250 MHz	100	—	1800	mVpp_se
		Differential AC-coupled 250 MHz < f_{IN}< 750 MHz	225	—	1800	mVpp_se
		Single-ended AC-coupled f_{IN} < 250 MHz	100	—	3600	mVpp_se
Slew Rate[2,3]	SR		400	—	—	V/µs
Duty Cycle	DC		40	—	60	%
Input Capacitance	C_{IN}	Single input pin	—	2.4	—	pF
Input Resistance Differential	$R_{IN-Diff}$		—	16	—	kΩ
Input Resistance Single-ended	R_{IN_SE}		—	8	—	kΩ
LVCMOS / Pulsed CMOS DC-Coupled Input Buffer (IN0, IN1, IN2)[4]						
Input Frequency	f_{IN_LVCMOS}		0.008	—	250	MHz
	$f_{IN\_PULSED\_CMOS}$		0.008	—	1	MHz
Input Voltage (see Si5348 Rev E Reference Manual for details)	V_{IL}	CMOS_HI_THR = 0	–0.2	—	0.4	V
	V_{IH}		0.8	—	—	V
	V_{IL}	CMOS_HI_THR = 1	–0.2	—	0.8	V
	V_{IH}		1	—	—	V
Slew Rate[2,3]	SR		400	—	—	V/µs
Minimum Pulse Width	PW	For Pulsed Input only	1.6	—	—	ns
Input Resistance	R_{IN}		—	8	—	kΩ
LVCMOS DC-Coupled Input Buffer (IN3, IN4)						
Input Frequency	f_{IN_LVCMOS}		0.008	—	2.048	MHz
Input Voltage	V_{IL}		—	—	0.3 x V_{DDIO}[5]	V
	V_{IH}		0.7 x V_{DDIO}[5]	—	—	V
Minimum Pulse Width	PW	Pulse Input	50	—	—	ns
Input Resistance	R_{IN}		—	20	—	kΩ

XA/XB (Crystal Recommended)						
XA/XB Frequency	f_{IN_REF}	Full operating range. Jitter performance may be reduced.	24.97	—	54.06	MHz
		Range for best jitter.	48	—	54	MHz
		TCXO frequency for SyncE applications. Jitter performance may be reduced.	—	40	—	MHz
Input Single-ended Voltage Swing	V_{IN_SE}		365	—	2000	mVpp_se
Input Differential Voltage Swing	V_{IN_DIFF}		365		2500	mVpp_diff
Slew Rate[2, 3]	SR		400	—	—	V/µs
Input Duty Cycle	DC		40	—	60	%

Note:

1. Voltage swing is specified as single-ended mVpp.



2. Recommended for specified jitter performance. Jitter performance could degrade if the minimum slew rate specification is not met (see the Si5348 Rev E Reference Manual).
3. Rise and fall times can be estimated using the following simplified equation: $tr/tf_{80\text{-}20} = ((0.8 - 0.2) \times V_{IN\_Vpp\_se}) / SR$.
4. Pulsed CMOS mode is intended primarily for single-ended LVCMOS input clocks < 1 MHz that must be dc-coupled because they have a duty cycle significantly less than 50%. A typical application example is a low-frequency video frame sync pulse.
5. VDDIO is determined by the IO_VDD_SEL bit to be either VDDA or VDD.

Table 6.4. Control Input Pin Specifications

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Si5348 Control Input Pins (I2C_SEL, A0/CSb, A1/SDO, SDA/SDIO, SCLK, RSTb, OE0b, OE1b, OE2b, FINC)						
Input Voltage	V_{IL}		—	—	0.3 × V_{DDIO}[1]	V
	V_{IH}		0.7 × V_{DDIO}[1]	—	—	V
Input Capacitance	C_{IN}		—	1.5	—	pF
Input Resistance	R_L		—	20	—	kΩ
Minimum Pulse Width	PW	RSTb, FINC	100	—	—	ns
Update Rate	F_{UR}	FINC	—	—	1	MHz
Si5348 Control Input Pin (FDEC)						
Input Voltage	V_{IL}		—	—	0.3 × V_{DDS}	V
	V_{IH}		0.7 × V_{DDS}	—	—	V
Input Capacitance	C_{IN}		—	1.5	—	pF
Minimum Pulse Width	PW	FDEC	100	—	—	ns
Update Rate	F_{UR}	FDEC	—	—	1	MHz

Note:
1. V_{DDIO} is determined by the IO_VDD_SEL bit. It is selectable as V_{DDA} or V_{DD}.

Table 6.5. Differential Clock Output Specifications

Parameter	Symbol	Test Condition		Min	Typ	Max	Unit
Output Frequency	f_{OUT}			0.0001	—	718.5	MHz
	f_{OUT1Hz}	1 PPS signal only available on Output 6			1		Hz
Duty Cycle	DC	f_{OUT} < 400 MHz		48	—	52	%
		400 MHz < f_{OUT} < 718.5 MHz		45	—	55	%
Output-Output Skew Using Same DSPLL	T_{SKS}	Output clocks at 370 MHz in LVDS differential format connected to the same DSPLL.		—	—	75	ps
OUT-OUTb Skew	T_{SK_OUT}	Measured from the positive to negative output pins		—	0	50	ps
Output Voltage Amplitude[1]	V_{OUT}	V_{DDO} = 3.3 V, 2.5 V, or 1.8 V	LVDS	350	430	510	mVpp_se
		V_{DDO} = 3.3 V, or 2.5 V	LVPECL	640	750	900	

Parameter	Symbol	Test Condition		Min	Typ	Max	Unit
Common Mode Voltage[1]	V_{CM}	V_{DDO} = 3.3 V	LVDS	1.10	1.20	1.30	V
			LVPECL	1.90	2.00	2.10	
		V_{DDO} = 2.5 V	LVPECL, LVDS	1.10	1.20	1.30	V
		V_{DDO} = 1.8 V	sub-LVDS	0.80	0.90	1.00	V
Rise and Fall Times (20% to 80%)	t_R/t_F			—	100	150	ps
Differential Output Impedance	Z_O			—	100	—	Ω
Power Supply Noise Rejection[2]	PSRR	10 kHz sinusoidal noise		—	–101	—	dBc
		100 kHz sinusoidal noise		—	–96	—	dBc
		500 kHz sinusoidal noise		—	–99	—	dBc
		1 MHz sinusoidal noise		—	–97	—	dBc
Output-output Crosstalk[3]	XTALK			—	–72	—	dBc

Note:

1. Output amplitude and common mode settings are programmable through register settings and can be stored in NVM. Each output driver can be programmed independently. Note that the maximum LVDS single-ended amplitude can be up to 110 mV higher than the TIA/EIA-644 maximum. Refer to the Si5348 Rev E Reference Manual for recommended settings. Not all combinations of voltage amplitude and common mode voltages settings are possible.
2. Measured for 156.25 MHz carrier frequency. 100 mVpp of sinewave noise added to VDDO running at 3.3 V and noise spur amplitude measured.
3. Measured across two adjacent outputs, both in LVDS mode, with the victim running at 155.52 MHz and the aggressor at 156.25 MHz. Refer to application note, AN862: Optimizing Si534x Jitter Performance in Next Generation Internet Infrastructure Systems, guidance on crosstalk minimization. Note that all active outputs must be terminated when measuring crosstalk.

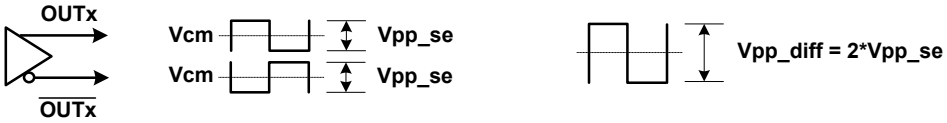


Table 6.6. LVCMOS Clock Output Specifications

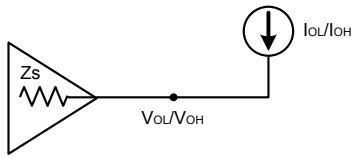
Parameter	Symbol	Test Condition		Min	Typ	Max	Unit
Output Frequency	f_{OUT}			0.0001	—	250	MHz
	f_{OUT1Hz}	Only Available on Output 6			1		Hz
Duty Cycle	DC	f_{OUT} <100 MHz		48	—	52	%
		100 MHz < f_{OUT} < 250 MHz		45	—	55	
Output Voltage High[1, 2, 3]	V_{OH}	V_{DDO} = 3.3 V					
		OUTx_CMOS_DRV=1	I_{OH} = –10 mA	V_{DDO} × 0.85	—	—	V
		OUTx_CMOS_DRV=2	I_{OH} = –12 mA		—	—	
		OUTx_CMOS_DRV=3	I_{OH} = –17 mA		—	—	
		V_{DDO} = 2.5 V					
		OUTx_CMOS_DRV=1	I_{OH} = –6 mA	V_{DDO} × 0.85	—	—	V
		OUTx_CMOS_DRV=2	I_{OH} = –8 mA		—	—	
		OUTx_CMOS_DRV=3	I_{OH} = –11 mA		—	—	
		V_{DDO} = 1.8 V					
		OUTx_CMOS_DRV=2	I_{OH} = –4 mA	V_{DDO} × 0.85	—	—	V
		OUTx_CMOS_DRV=3	I_{OH} = –5 mA		—	—	
Output Voltage Low[1, 2, 3]	V_{OL}	V_{DDO} = 3.3 V					
		OUTx_CMOS_DRV=1	I_{OL} = 10 mA	—	—	V_{DDO} × 0.15	V
		OUTx_CMOS_DRV=2	I_{OL} = 12 mA	—	—		
		OUTx_CMOS_DRV=3	I_{OL} = 17 mA	—	—		
		V_{DDO} = 2.5 V					
		OUTx_CMOS_DRV=1	I_{OL} = 6 mA	—	—	V_{DDO} × 0.15	V
		OUTx_CMOS_DRV=2	I_{OL} = 8 mA	—	—		
		OUTx_CMOS_DRV=3	I_{OL} = 11 mA	—	—		
		V_{DDO} = 1.8 V					
		OUTx_CMOS_DRV=2	I_{OL} = 4 mA	—	—	V_{DDO} × 0.15	V
		OUTx_CMOS_DRV=3	I_{OL} = 5 mA	—	—		
LVCMOS Rise and Fall Times[3] (20% to 80%)	tr/tf	V_{DDO} = 3.3 V		—	400	600	ps
		V_{DDO} = 2.5 V		—	450	600	ps
		V_{DDO} = 1.8 V		—	550	750	ps

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit

Note:

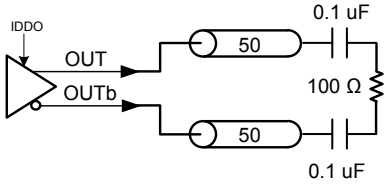
1. Driver strength is a register programmable setting and stored in NVM. Options are OUTx_CMOS_DRV = 1, 2, 3. Refer to the Si5348 Rev E Reference Manual for more details on register settings.
2. I_{OL}/I_{OH} is measured at V_{OL}/V_{OH} as shown in the dc test configuration.

DC Test Configuration



3. A 5 pF capacitive load is assumed. The LVCMOS outputs were set to OUTx_CMOS_DRV = 3, at 156.25 MHz.

Differential Output Test Configuration



LVCMOS Output Test Configuration

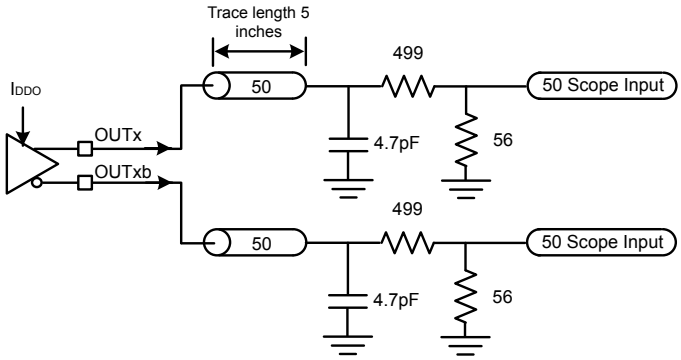


Table 6.7. Output Status Pin Specifications

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Si5348 Status Output Pins (LOL_Cb, LOL_Db, INTRb, LOS1b, LOS2b, SDA/SDIO[2], A1/SDO)						
Output Voltage	V_{OH}	I_{OH} = –2 mA	V_{DDIO}[1] × 0.85	—	—	V
	V_{OL}	I_{OL} = 2 mA	—	—	V_{DDIO}[1] × 0.15	V
Si5348 Status Output Pins (LOL_Ab, LOS0b)						
Output Voltage	V_{OH}	I_{OH} = –2 mA	V_{DDS} × 0.85	—	—	V
	V_{OL}	I_{OL} = 2 mA	—	—	V_{DDS} × 0.15	V

Note:

1. V_{DDIO} is determined by the IO_VDD_SEL bit. It is selectable as V_{DDA} or V_{DD}. Users normally select this option in the ClockBuilder Pro GUI. Alternatively, refer to the Si5348 Rev E Reference Manual for more details on register settings.
2. The V_{OH} specification does not apply to the open-drain SDA/SDIO output when the serial interface is in I^2C mode or is unused with I2C_SEL pulled high. V_{OL} remains valid in all cases.

Table 6.8. Performance Characteristics

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
PLL Loop Bandwidth Programming Range[1]	f_{BW}		0.001	—	4000	Hz
Initial Start-Up Time	t_{START}	Time from power-up to when the device generates free-running clocks	—	30	45	ms
PLL Lock Time[2]	t_{ACQ}	With Fastlock enabled	—	280	300	ms
POR to Serial Interface Ready[3]	t_{RDY}		—	—	15	ms
Jitter Peaking	J_{PK}	Measured with a frequency plan running a 25 MHz input, 25 MHz output, and a loop bandwidth of 4 Hz	—	—	0.1	dB
Jitter Tolerance[4]	J_{TOL}	Compliant with G.8262 Options 1&2 Carrier Frequency = 10.3125 GHz (10 Gbe) Jitter Modulation Frequency = 10 Hz	—	>5000	—	UI pk-pk
Maximum Phase Transient During a Hitless Switch[5]	t_{SWITCH}	Single automatic switch between two 8 kHz inputs, DSPLL BW = 400 Hz	—	0.5	1.2	ns
		Single automatic switch between two 2 MHz inputs, DSPLL BW = 400 Hz	—	0.2	0.3	ns
		Single manual switch between two 8 kHz inputs, DSPLL BW = 400 Hz	—	0.5	1.0	ns
		Single manual switch between two 2 MHz inputs, DSPLL BW = 400 Hz	—	0.2	0.25	ns
Pull-in Range	ω_P		—	500	—	ppm
RMS Phase Jitter[6]	J_{GEN}	12 kHz to 20 MHz	—	95	125	fs rms

Note:

1. Actual loop bandwidth might be lower; refer to CBPro for actual value on your frequency plan.
2. Lock Time can vary significantly depending on several parameters, such as bandwidths, LOL thresholds, etc. For this case, lock time was measured with fastlock bandwidth set to 100 Hz, LOL set/clear thresholds of 6/0.6 ppm respectively, using IN0 as clock reference by removing the reference and enabling it again, then measuring the delta time between the first rising edge of the clock reference and the LOL indicator de-assertion.
3. Measured as time from valid VDD/VDDA rails (90% of their value) to when the serial interface is ready to respond to commands.
4. For details on this test, see the jitter tolerance test results in the Si5348 Rev. E ITU-T G.8262 Compliance Report.
5. Maximum Phase Transient during Hitless Switch will degrade with lower Fpfd. Fpfd frequencies greater than 500 kHz will result in lower phase transients. Consult your CBPro Design report for the Fpfd frequency of your configuration. Measurements taken with cover placed over crystal to reduce wander. See the Si5348 Rev E Reference Manual for further details.
6. Jitter generation test conditions: f_{IN} = 19.44 MHz, f_{OUT} = 156.25 MHz LVPECL.

Table 6.9. I^2C Timing Specifications (SCL,SDA)

Parameter	Symbol	Test Condition	Standard Mode 100 kbps		Fast Mode 400 kbps		Unit
			Min	Max	Min	Max	
SCL Clock Frequency	f_{SCL}		—	100	—	400	kHz
SMBus Timeout	—		25	35	25	35	ms
Hold time (repeated) START condition	$t_{HD:STA}$		4.0	—	0.6	—	µs
Low period of the SCL clock	t_{LOW}		4.7	—	1.3	—	µs
HIGH period of the SCL clock	t_{HIGH}		4.0	—	0.6	—	µs
Set-up time for a repeated START condition	$t_{SU:STA}$		4.7	—	0.6	—	µs
Data hold time	$t_{HD:DAT}$		100	—	100	—	ns
Data set-up time	$t_{SU:DAT}$		250	—	100	—	ns
Rise time of both SDA and SCL signals	t_r		—	1000	20	300	ns
Fall time of both SDA and SCL signals	t_f		—	300	—	300	ns
Set-up time for STOP condition	$t_{SU:STO}$		4.0	—	0.6	—	µs
Bus free time between a STOP and START condition	t_{BUF}		4.7	—	1.3	—	µs
Data valid time	$t_{VD:DAT}$		—	3.45	—	0.9	µs
Data valid acknowledge time	$t_{VD:ACK}$		—	3.45	—	0.9	µs

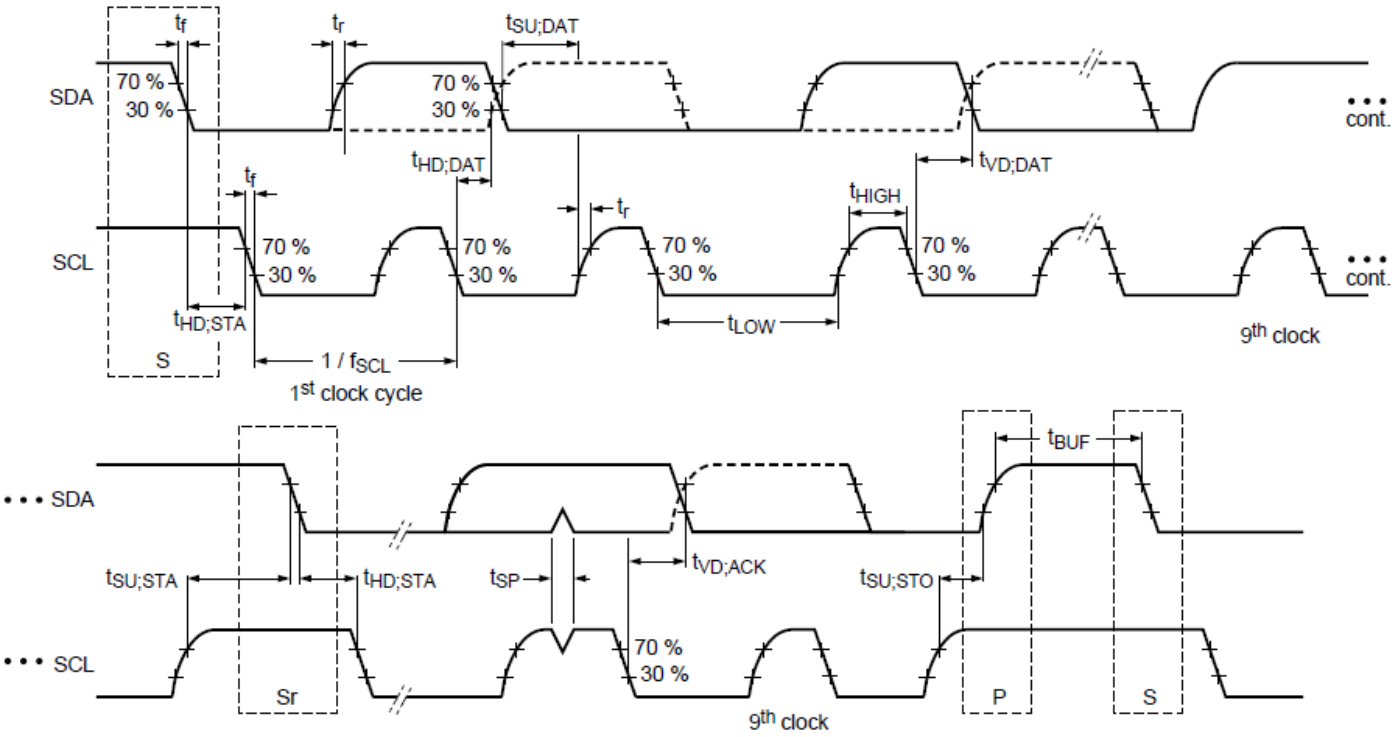


Figure 6.1. I²C Serial Port Timing Standard and Fast Modes

Table 6.10. SPI Timing Specifications (4-Wire)

Parameter	Symbol	Min	Typ	Max	Unit
SCLK Frequency	f_{SPI}	—	—	20	MHz
SCLK Duty Cycle	T_{DC}	40	—	60	%
SCLK Period	T_C	50	—	—	ns
Delay Time, SCLK Fall to SDIO Turn-on	T_{D1}	—	—	18	ns
Delay Time, SCLK Fall to SDIO Next-bit	T_{D2}	—	—	15	ns
Delay Time, CSb Rise to SDIO Tri-State	T_{D3}	—	—	15	ns
Setup Time, CSb to SCLK	T_{SU1}	5	—	—	ns
Hold Time, SCLK fall to CSb	T_{H1}	5	—	—	ns
Setup Time, SDI to SCLK Rise	T_{SU2}	5	—	—	ns
Hold Time, SDI to SCLK Rise	T_{H2}	5	—	—	ns
Delay Time Between Chip Selects (CSb)	T_{CS}	2	—	—	T_C

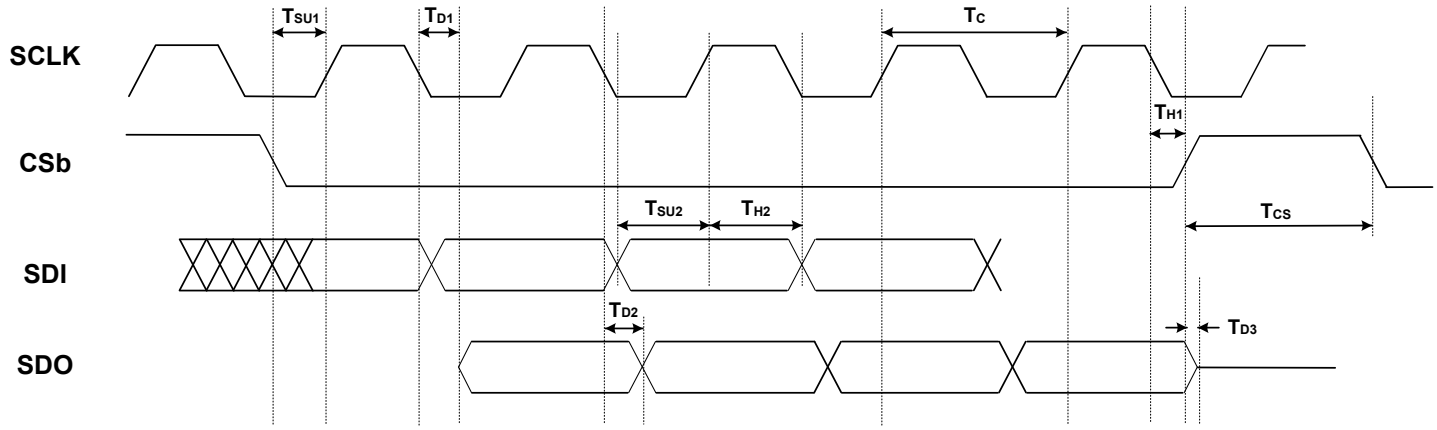


Figure 6.2. 4-Wire SPI Serial Interface Timing

Table 6.11. SPI Timing Specifications (3-Wire)

Parameter	Symbol	Min	Typ	Max	Units
SCLK Frequency	f_{SPI}	—	—	20	MHz
SCLK Duty Cycle	T_{DC}	40	—	60	%
SCLK Period	T_C	50	—	—	ns
Delay Time, SCLK Fall to SDIO Turn-on	T_{D1}	—	—	20	ns
Delay Time, SCLK Fall to SDIO Next-bit	T_{D2}	—	—	15	ns
Delay Time, CSb Rise to SDIO Tri-State	T_{D3}	—	—	15	ns
Setup Time, CSb to SCLK	T_{SU1}	5	—	—	ns
Hold Time, SCLK Fall to CSb	T_{H1}	5	—	—	ns
Setup Time, SDI to SCLK Rise	T_{SU2}	5	—	—	ns
Hold Time, SDI to SCLK Rise	T_{H2}	5	—	—	ns
Delay Time Between Chip Selects (CSb)	T_{CS}	2	—	—	T_C

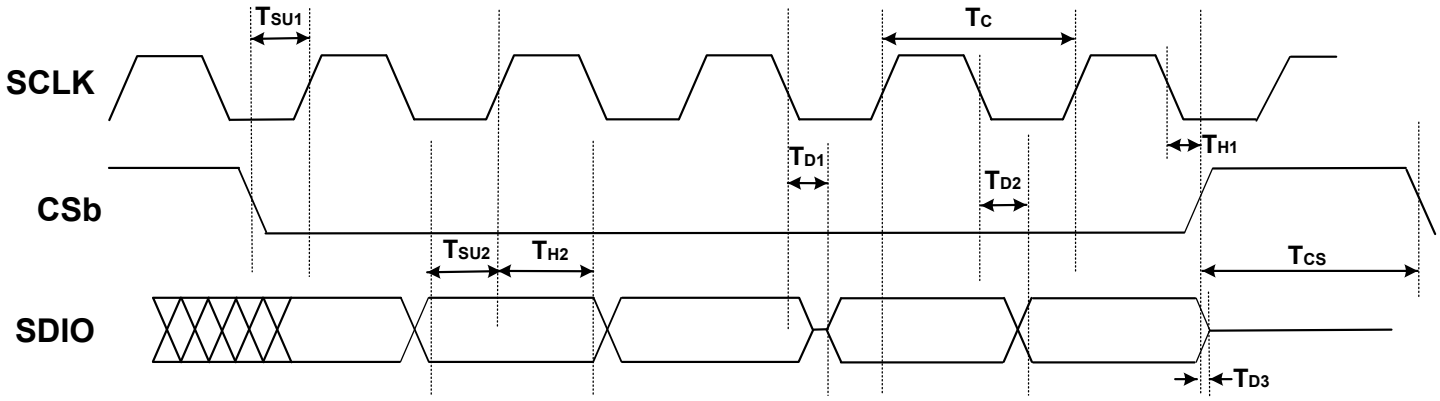


Figure 6.3. 3-Wire SPI Serial Interface Timing

Table 6.12. Crystal Specifications[1]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Crystal Frequency Range	f_{XTAL}		48	—	54	MHz
Load Capacitance	C_L		—	8	—	pF
Crystal Drive Level	d_L		—	—	200	µW
Equivalent Series Resistance Shunt Capacitance	r_{ESR} C_O	Refer to the Si5348 Rev E Reference Manual to determine ESR and shunt capacitance requirements.				

Note:
1. Refer to the Si534x/8x Recommended Crystal, TCXO and OCXOs Reference Manual for recommended 48 to 54 MHz crystals. The Si5348 is designed to work only with crystals that meet these specifications, and not with XOs.

Table 6.13. Thermal Characteristics

Parameter	Symbol	Test Condition[1]	Value	Unit
Si5348-64QFN				
Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air	22	°C/W
		Air Flow 1 m/s	19.4	
		Air Flow 2 m/s	18.3	
Thermal Resistance Junction to Case	Θ_{JC}		9.5	
Thermal Resistance Junction to Board	Θ_{JB}		9.4	
	Ψ_{JB}		9.3	
Thermal Resistance Junction to Top Center	Ψ_{JT}		0.2	

Note:
1. Based on PCB Dimension: 3" x 4.5", PCB Thickness: 1.6 mm, PCB Land/Via: 36, Number of Cu Layers: 4.

Table 6.14. Absolute Maximum Ratings[1, 2, 3, 4]

Parameter	Symbol	Test Condition	Value	Unit
Storage Temperature Range	T_{STG}		–55 to 150	°C
DC Supply Voltage	V_{DD}		–0.5 to 3.8	V
	V_{DDA}		–0.5 to 3.8	V
	V_{DDO}		–0.5 to 3.8	V
	V_{DDS}		–0.5 to 3.8	V
Input Voltage Range	V_{I1}[5]	IN0 - IN4, REF	–1.0 to V_{DDA} + 0.3	V
	V_{I2}	RSTb, OE0b, OE1b, OE2b, I2C_SEL,FINC, FDEC, A1/ SDO, SDA/SDIO, SCLK, A0/ CSb,	–0.5 to V_{DDA} + 0.3	V
	V_{I3}	XA/XB	–0.5 to 2.7	V
Latch-up Tolerance	LU		JESD78 Compliant	
ESD Tolerance	HBM	100 pF, 1.5 kΩ	2.0	kV
Max Junction Temperature in Operation	T_{JCT}		125	°C
Soldering Temperature (Pb-free profile)[3]	T_{PEAK}		260	°C
Soldering Temperature Time at T_{PEAK} (Pb-free profile)[4]	T_P		20-40	s

Note:

1. Permanent device damage may occur if the absolute maximum ratings are exceeded. Functional operation should be restricted to the conditions as specified in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
2. 64-QFN package is RoHS-6 compliant.
3. For detailed MSL and packaging information, go to www.silabs.com/support/quality/pages/RoHSInformation.aspx.
4. The device is compliant with JEDEC J-STD-020.
5. The minimum voltage at these pins can be as low as –1.0 V when an ac input signal of 8 kHz or greater is applied. See Table 6.3 Input Clock Specifications on page 26 spec for Single-Ended AC-Coupled f_{IN} < 250 MHz.

7. Typical Application Schematic

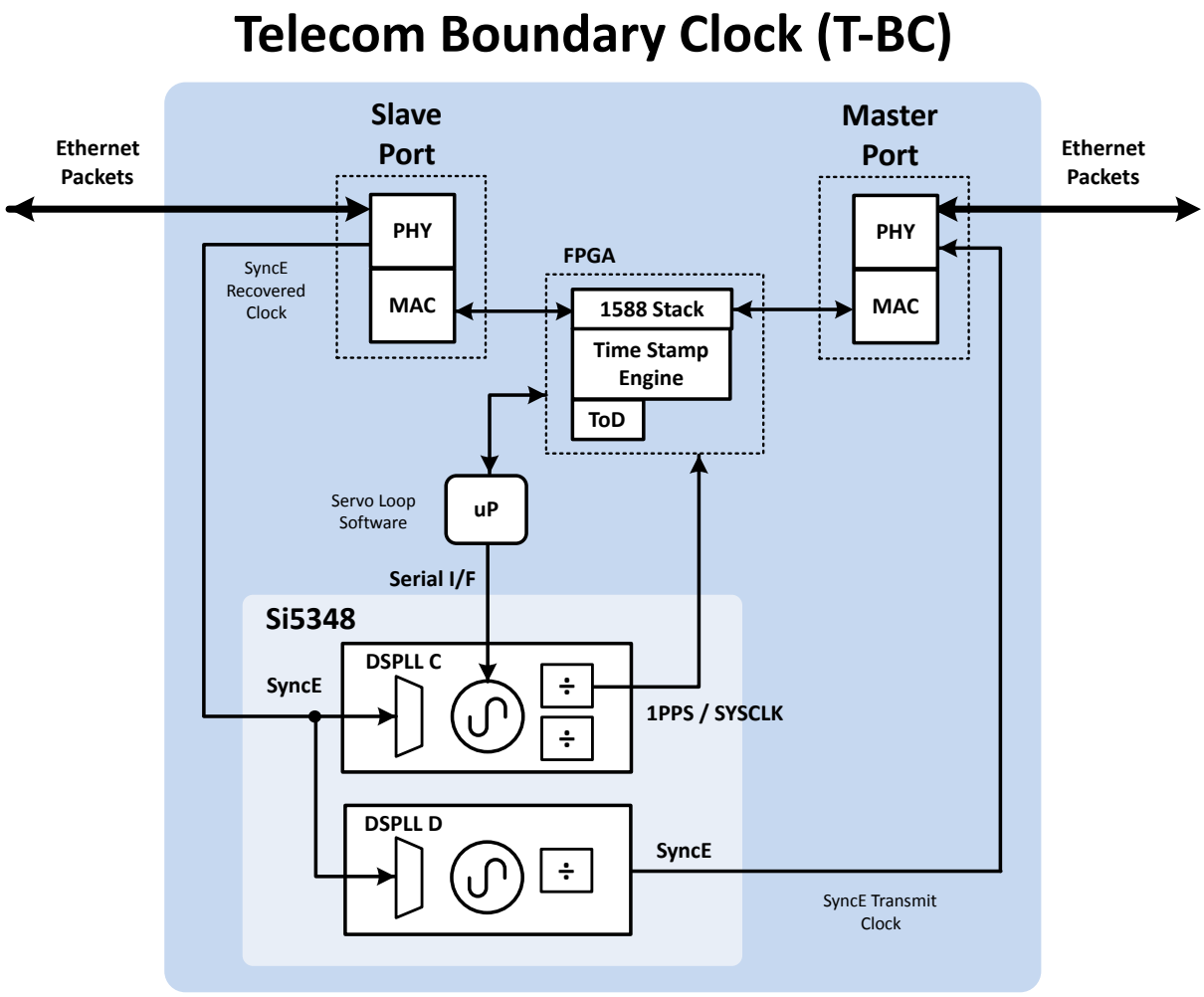


Figure 7.1. Using the Si5348 as a Telecom Boundary Clock

8. Detailed Block Diagram

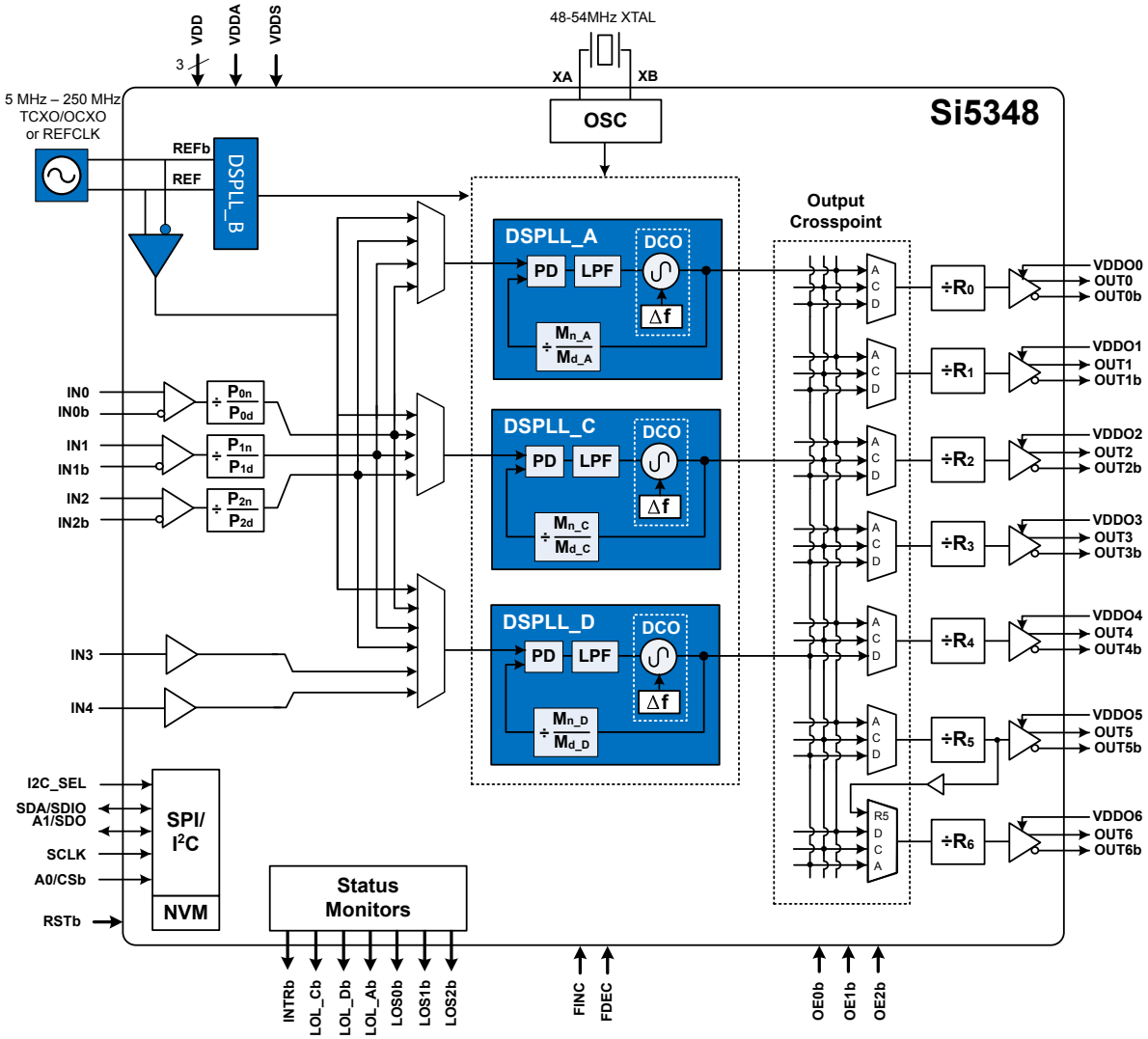


Figure 8.1. Si5348-E Detailed Block Diagram

9. Typical Operating Characteristics (Jitter and Phase Noise)

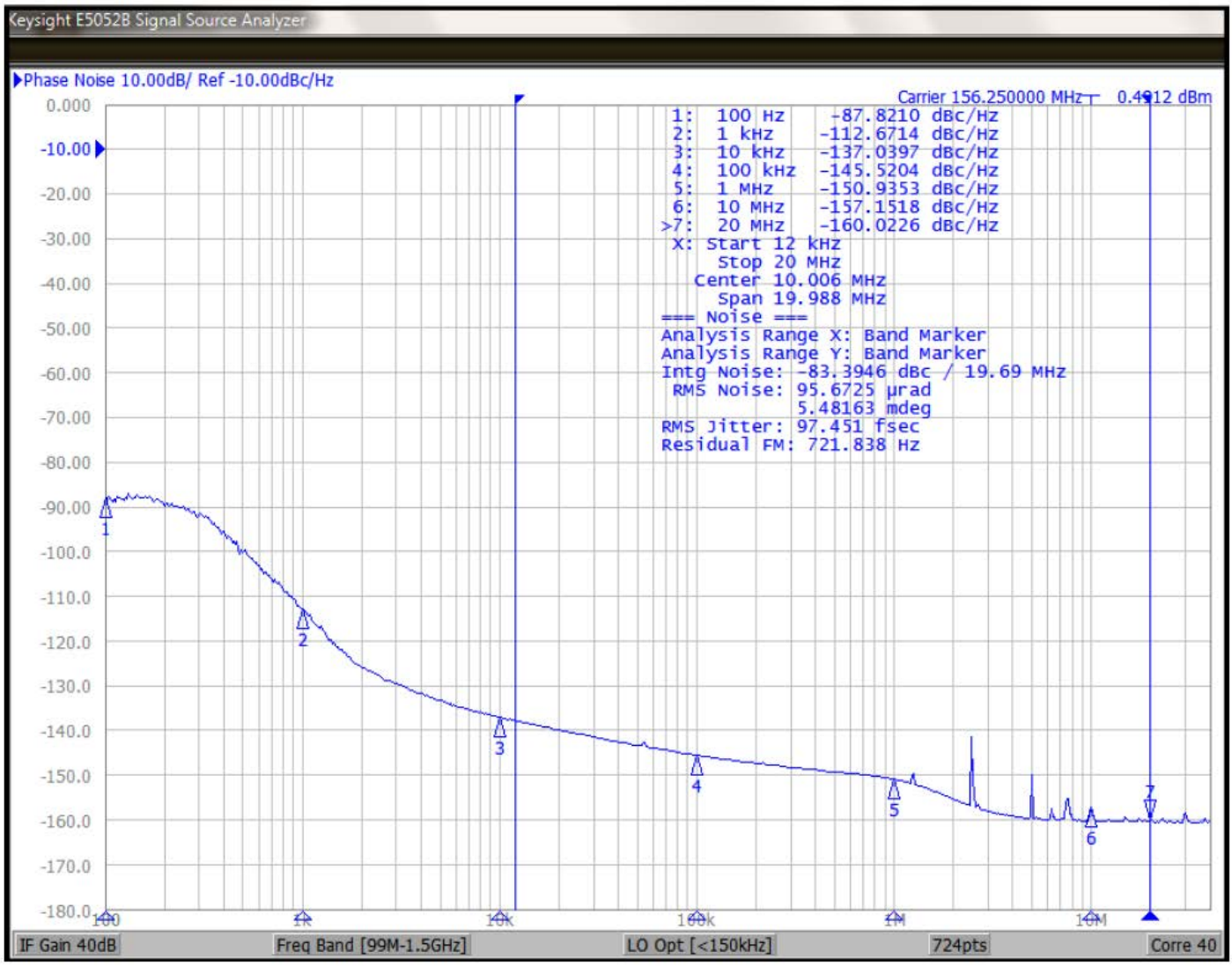


Figure 9.1. Input = 25 MHz; Output = 156.25 MHz, 2.5 V LVDS with Rakon 12.8 MHz Reference

10. Pin Descriptions

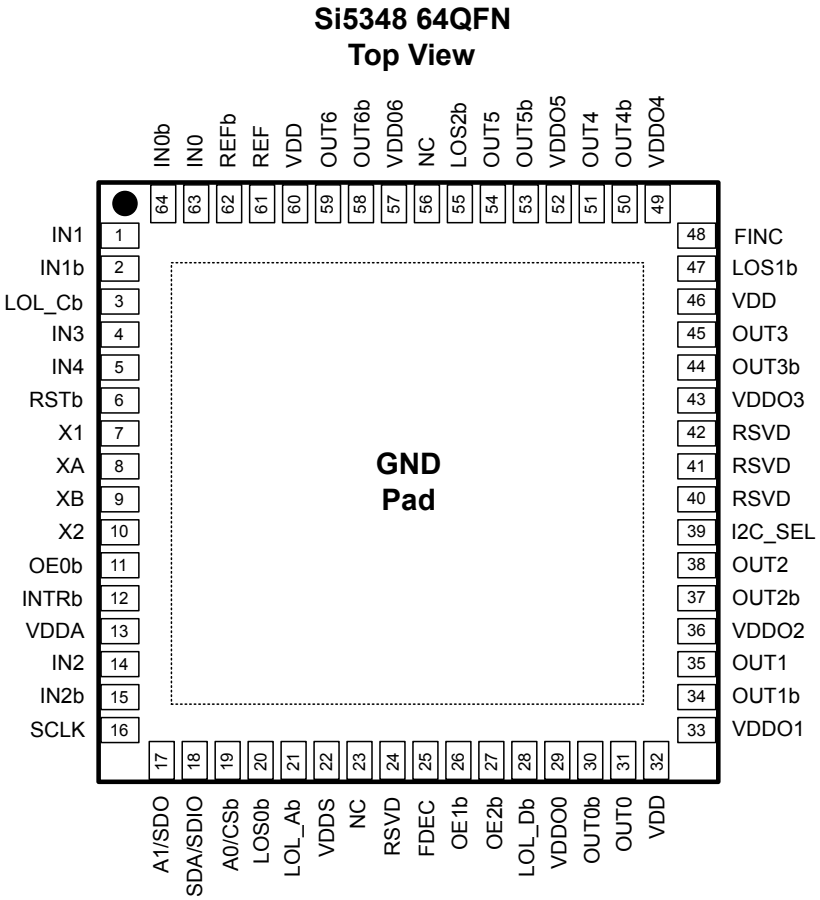


Figure 10.1. Si5348 Pin Descriptions

Table 10.1. Si5348 Pin Descriptions [1]

Pin Name[1]	Pin Number	Pin Type [2]	Function
Inputs			
XA	8	I	**Crystal Input**. Input pin for external crystal (XTAL).
XB	9	I	
X1	7	I	**XTAL Shield**. Connect these pins directly to the XTAL ground pins. The XTAL ground pins should be separated from the PCB ground plane. Refer to the Si5348 Rev E Reference Manual for layout guidelines.
X2	10	I	
IN0	63	I	**Clock Inputs**. IN0-IN2 accept an input clock for synchronizing the device. They support both differential and single-ended clock signals. Refer to Input Configuration and Terminations for information on input termination options. These pins are high-impedance and must be terminated externally. The negative side of the differential input must be grounded through a capacitor when accepting a single-ended clock. IN3 and IN4 only support single-ended LVCMOS signals.These pins are high-impedance and must be terminated externally. Unused inputs can be disabled by register configuration and the pins left unconnected.
IN0b	64	I	
IN1	1	I	
IN1b	2	I	
IN2	14	I	
IN2b	15	I	
IN3	4	I	
IN4	5	I	
REF	61	I	**Reference Input**. This input accepts a reference clock from a stable source (eg. TCXO or OCXO) that is used to determine free-run frequency accuracy and stability during free-run or holdover of the DSPLL or DCO. These inputs can accept differential or single-ended connections. Refer to the Si534x/8x Recommended Crystal, TCXO, and OCXOs Reference Manual for information on recommended TCXOs and OCXOs.
REFb	62	I	
Outputs			
OUT0	31	O	**Output Clocks**. These output clocks support a programmable signal amplitude and common mode voltage. Desired output signal format is configurable using register control.Termination recommendations are provided in 4.9 Outputs. Unused outputs should be left unconnected.
OUT0b	30	O	
OUT1	35	O	
OUT1b	34	O	
OUT2	38	O	
OUT2b	37	O	
OUT3	45	O	
OUT3b	44	O	
OUT4	51	O	
OUT4b	50	O	
OUT5	54	O	
OUT5b	53	O	
OUT6	59	O	
OUT6b	58	O	
Serial Interface			

Pin Name[1]	Pin Number	Pin Type [2]	Function
I2C_SEL	39	I	**I²C Select[3]**. This pin selects the serial interface mode as I²C (I2C_SEL = 1) or SPI (I2C_SEL = 0). This pin is internally pulled up to the voltage selected by the IO_VDD_SEL register bit. This pin is 3.3 V tolerant.
SDA/SDIO	18	I/O	**Serial Data Interface[3]**. This is the bidirectional data pin (SDA) for the I²C mode, or the bidirectional data pin (SDIO) in the 3-wire SPI mode, or the input data pin (SDI) in 4-wire SPI mode. When not in SPI mode, this pin must be pulled-up using an external resistor of at least 1 kΩ. No pull-up resistor is needed when in SPI mode unless the master SPI driver is open drain. This pin is 3.3 V tolerant.
A1/SDO	17	I/O	**Address Select 1/Serial Data Output[3]**. In I²C mode this pin functions as the A1 address input pin and does not have an internal pull up or pull down resistor. In 4-wire SPI mode, this is the serial data output (SDO) pin. and drives high to the voltage selected by the IO_VDD_SEL pin. This pin is 3.3 V tolerant. This pin must be pulled up externally when unused.
SCLK	16	I	**Serial Clock Input[3]**. This pin functions as the serial clock input for both I²C and SPI modes. This pin does not have an internal pull-up or pull-down. When in I²C mode or unused, this pin must be pulled-up using an external resistor of at least 1 kΩ. No pull-up resistor is needed when in SPI mode unless the SPI master driver is open drain. This pin is 3.3 V tolerant.
A0/CSb	19	I	**Address Select 0/Chip Select[3]**. This pin functions as the hardware controlled address A0 input pin in I²C mode. In SPI mode, this pin functions as the chip select input (active low). This pin is internally pulled-up by a 20 kΩ resistor to the voltage selected by the IO_VDD_SEL register bit. This pin is 3.3 V tolerant.
Control/Status			
INTRb	12	O	**Interrupt[3]**. This pin is asserted low when a change in device status has occurred. It should be left unconnected when not in use.
RSTb	6	I	**Device Reset[3]**. Active low input that performs power-on reset (POR) of the device. Resets all internal logic to a known state and forces the device registers to their default values. Clock outputs are disabled during reset. This pin is internally pulled-up.
OE0b	11	I	**Output Enable 0-2[3]**. These output enable pins have a programmable register mask which allows them to control any of the output clocks. By default the OE0b pin enables all output clocks and OE1b, OE2b have no control over the output clocks until register configured. These pins are internally pulled low and can be left unconnected when not in use.
OE1b	26	I	
OE2b	27	I	
LOL_Ab	21	O	**Loss of Lock_Ab[4]/Cb[3]/Db[3]**. These output pins indicate when DSPLL A, C, D is out-of-lock (low) or locked (high). They can be left unconnected when not in use.
LOL_Cb	3	O	
LOL_Db	28	O	
LOS0b	20	O	**Loss of Signal for 0b[4], 1b[3], 2b[3]**. These pins reflect the loss of signal register status bits for inputs (0b, 1b, 2b). These pins can be left unconnected when not in use.
LOS1b	47	O	
LOS2b	55	O	
FDEC	25	I	**Frequency Decrement Pin[4]**. This pin is used to step-down the output frequency of a selected DSPLL. The frequency change step size is register configurable. This pin does not have an internal pullup/pulldown and must be externally pulled high or low when unused.

Pin Name[1]	Pin Number	Pin Type [2]	Function
FINC	48	I	**Frequency Increment Pin**[3]. This pin is used to step-up the output frequency of a selected DSPLL. The frequency change step size is register configurable. The DSPLL(s) affected by the frequency change is determined by the M_FSTEP_MSK_PLLx register settings. This pin is pulled low internally and can be left unconnected when not in use.
RSVD	24	-	**Reserved**. These pins are connected to the die. Leave disconnected.
	40	-	
	41	-	
	42	-	
NC	23	-	**No Connect**. These pins are not connected to the die. Leave disconnected.
	56	-	
Power			
VDD	32	P	**Core Supply Voltage**. The device core operates from a 1.8 V supply. See the Si5348 Rev E Reference Manual for power supply filtering recommendations. A 0402 1 µF capacitor should be placed very near each of these pins.
	46		
	60		
VDDA	13	P	**Core Supply Voltage 3.3 V**. This core supply pin requires a 3.3 V power source. See the Si5348 Rev E Reference Manual for power supply filtering recommendations. A 0402 1 µF capacitor should be placed very near each of these pins.
VDDS	22	P	**Status Output Voltage**. The voltage on this pin determines VOL/VOH on the LOL_Ab and LOS0b status output pins, as well as the FDEC input. Connect to either 3.3 V or 1.8 V. A 0.1 µF bypass capacitor should be placed very close to this pin.
VDDO0	29	P	**Output Clock Supply Voltage 0-6**. Supply voltage (3.3 V, 2.5 V, 1.8 V) for OUTn outputs. Leave VDDO pins of unused output drivers unconnected. An alternate option is to connect the VDDO pin to a power supply and disable the output driver to minimize current consumption. A 0402 1 µF capacitor should be placed very near each of these pins.
VDDO1	33	P	
VDDO2	36	P	
VDDO3	43	P	
VDDO4	49	P	
VDDO5	52	P	
VDDO6	57	P	
GND PAD	-	P	**Ground Pad**. This pad provides connection to ground and must be connected for proper operation. Use as many vias as practical and keep the via length to an internal ground plan as short as possible.

Note:

1. Refer to the Si5348 Rev E Reference Manual for more information on register setting names.
2. I = Input, O = Output, P = Power.
3. The IO_VDD_SEL control bit (0x0943 bit 0) selects 3.3 V or 1.8 V operation.
4. The voltage on the VDDS pin(s) determines 3.3 V or 1.8 V operation.

11. Package Outline

The figure below illustrates the package details for the Si5348. The table below lists the values for the dimensions shown in the illustration.

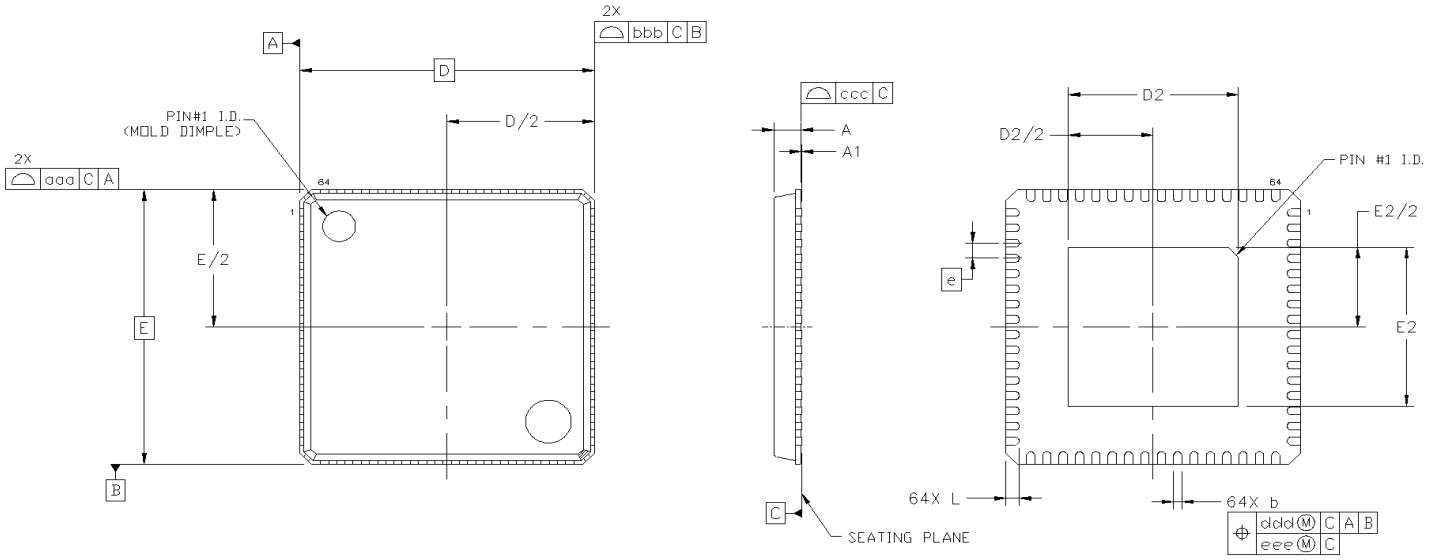


Figure 11.1. Si5348 9x9 mm 64-Pin Quad Flat No-Lead (QFN)

Table 11.1. Package Dimensions

Dimension	Min	Nom	Max
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
b	0.18	0.25	0.30
D		9.00 BSC	
D2	5.10	5.20	5.30
e		0.50 BSC	
E		9.00 BSC	
E2	5.10	5.20	5.30
L	0.30	0.40	0.50
aaa	—	—	0.15
bbb	—	—	0.10
ccc	—	—	0.08
ddd	—	—	0.10
eee	—	—	0.05

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to the JEDEC Solid State Outline MO-220.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

12. PCB Land Pattern

The figure below illustrates the PCB land pattern details for the devices. The table below lists the values for the dimensions shown in the illustration. Refer to the Si5348 Rev E Reference Manual for information about thermal via recommendations.

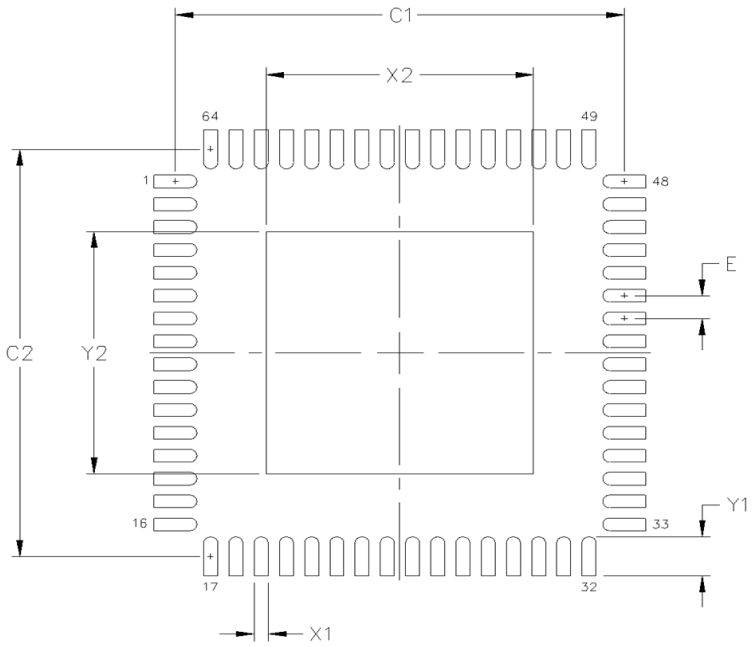


Figure 12.1. Si5348 PCB Land Pattern

Table 12.1. PCB Land Pattern Dimensions

Dimension	Si5348 (Max)
C1	8.90
C2	8.90
E	0.50
X1	0.30
Y1	0.85
X2	5.30
Y2	5.30

Note:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. This Land Pattern Design is based on the IPC-7351 guidelines.
3. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition is calculated based on a fabrication Allowance of 0.05 mm.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.
4. A 3x3 array of 1.25 mm square openings on 1.80 mm pitch should be used for the center ground pad.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

13. Top Marking

Figure 13.1. Si5348 Top Marking

Table 13.1. Top Marking

Line	Characters	Description
1	Si5348g-	Base part number and Device Grade. Si5348: Packet Network Synchronizer for SyncE/1588; 64-QFN g = Device Grade. See 3. Ordering Guide for more information. – = Dash character.
2	Rxxxxx-GM	R = Product revision. (See 3. Ordering Guide for current revision.) xxxxx = Customer specific NVM sequence number. (Optional NVM code assigned for custom, factory pre-programmed devices. Characters are not included for standard, factory default configured devices). See 3. Ordering Guide for more information. -GM = Package (QFN) and temperature range (–40 to +85 °C).
3	YYWWTTTTTT	YYWW = Characters correspond to the year (YY) and work week (WW) of package assembly. TTTTTT = Manufacturing trace code.
4	Circle w/ 1.6 mm (64-QFN) diameter	Pin 1 indicator; left-justified
	e4 TW	Pb-free symbol; Center-Justified TW = Taiwan; Country of Origin (ISO Abbreviation)

14. Device Errata

Please log in or register at www.silabs.com to access device errata documents.

15. Revision History

Revision 0.95

September, 2018

Initial release Revision E.

ClockBuilder Pro

One-click access to Timing tools, documentation, software, source code libraries & more. Available for Windows and iOS (CBGo only).

www.silabs.com/CBPro

Timing Portfolio
www.silabs.com/timing

SW/HW
www.silabs.com/CBPro

Quality
www.silabs.com/quality

Support and Community
community.silabs.com

Silicon Laboratories Inc.
400 West Cesar Chavez
Austin, TX 78701
USA

http://www.silabs.com